

Radiation Effects in Silicon Photonics

Micro-Ring Modulators and

Waveguides for High-Energy Physics

Daniele Alfiero

Seminar

University of Birmingham



daniele.alfiero@cern.ch

28.05.2026





- **Introduction**

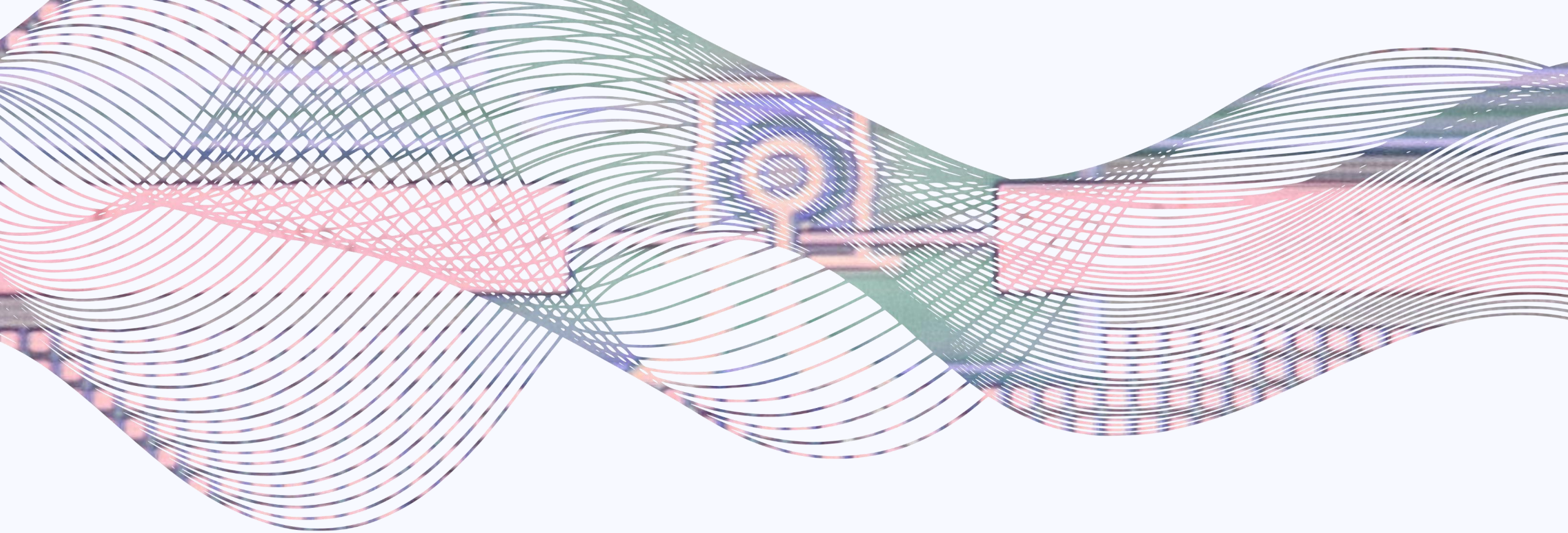
- Silicon Photonics for high-speed links in particle detectors
- Ring modulators and waveguides

- **Irradiation campaigns**

- X-ray test on ring modulators:
 - Electro-optic frequency response
 - Localized thermal annealing
- Neutron and X-ray tests on waveguides:
 - Radiation-induced attenuation (RIA)
- Heavy ion test on waveguides:
 - Optical single-event transients (OSETs)
 - TCAD simulations

- **Conclusions and future work**





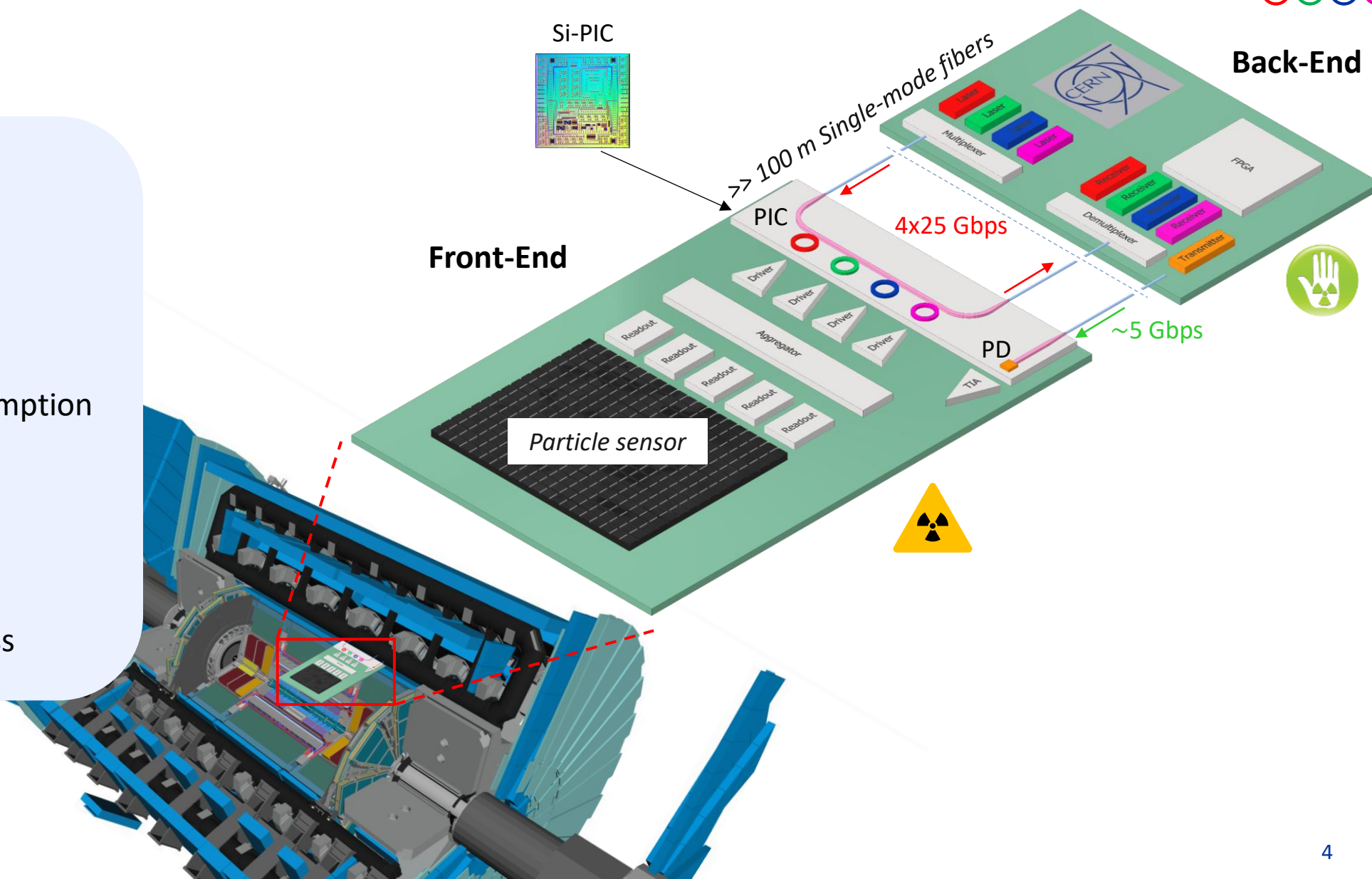
Introduction

Silicon Photonics for High-Energy Physics



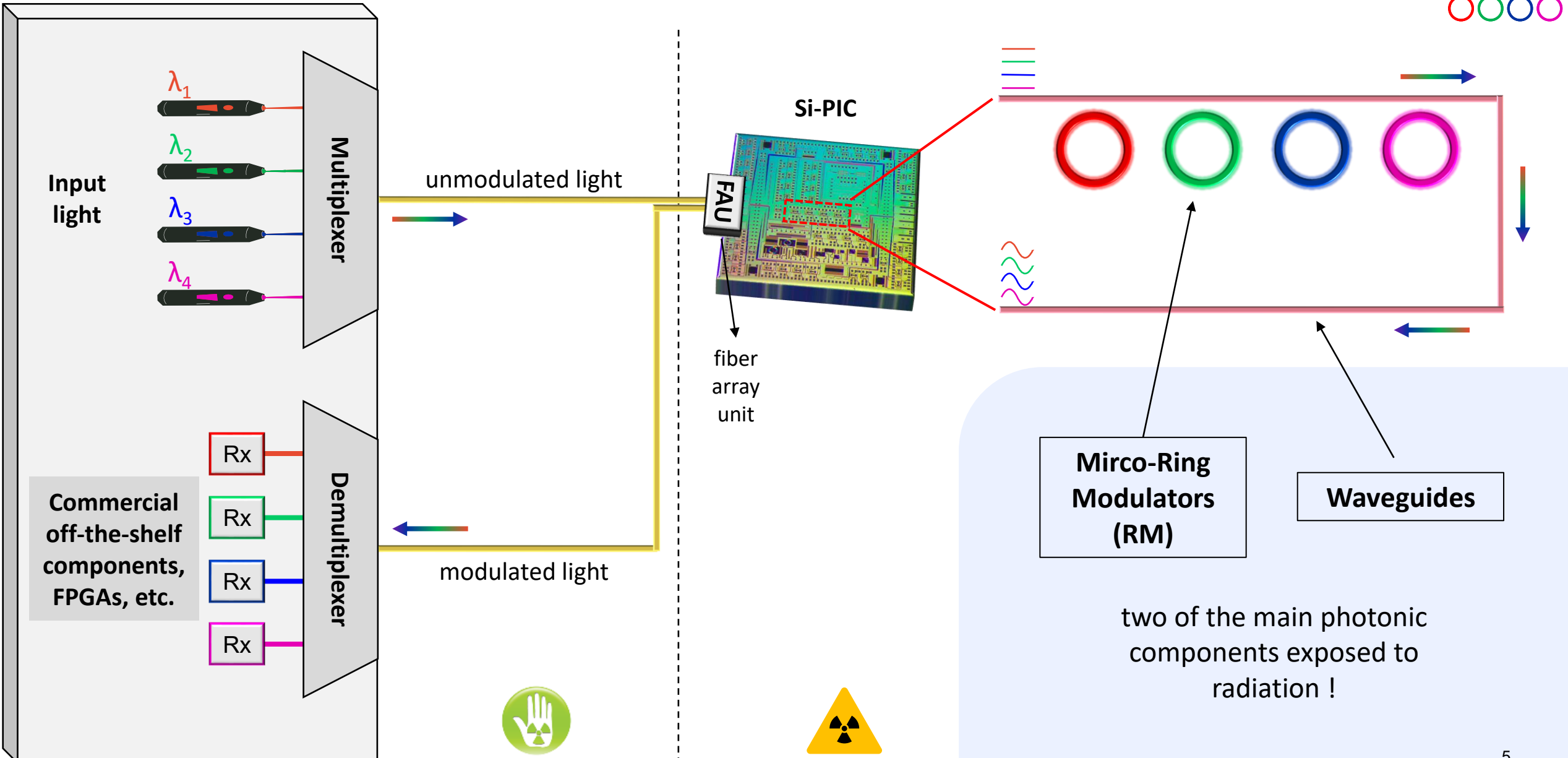
Silicon Photonics

- ✓ High-speed data transmission
- ✓ Low mass
- ✓ Low power consumption
- ✓ CMOS compatible process flow
- ? Radiation hardness



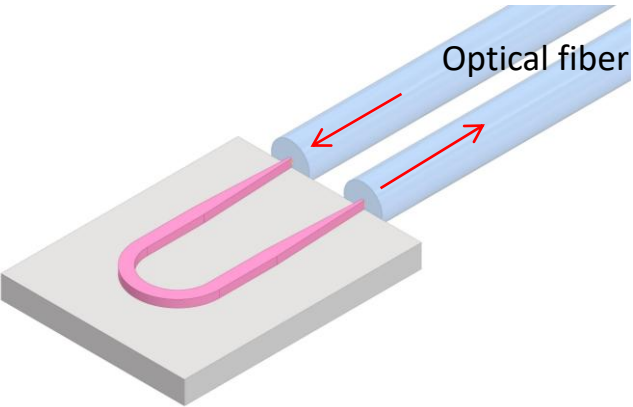
PIC: Photonic Integrated Circuit
PD: Photodiode

Introduction – Overview of a SiPh-based transceiver

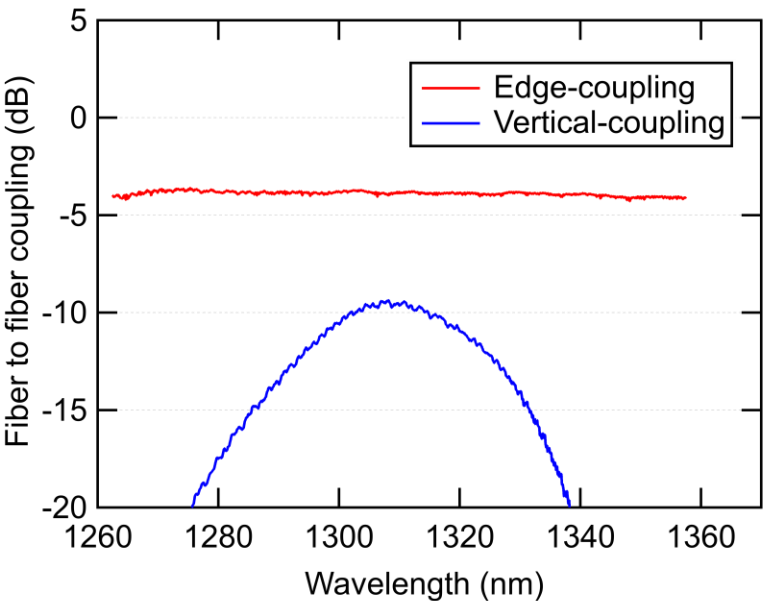
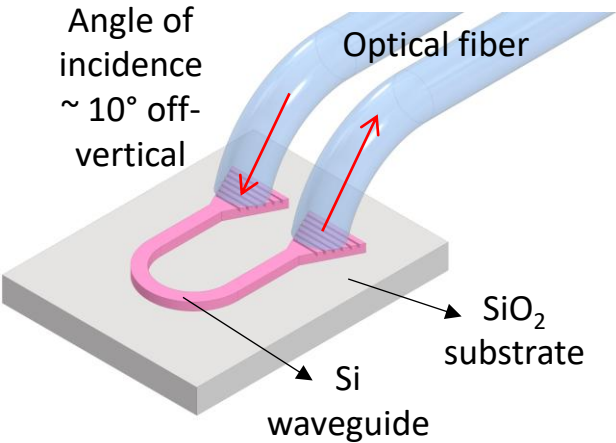




Edge coupler

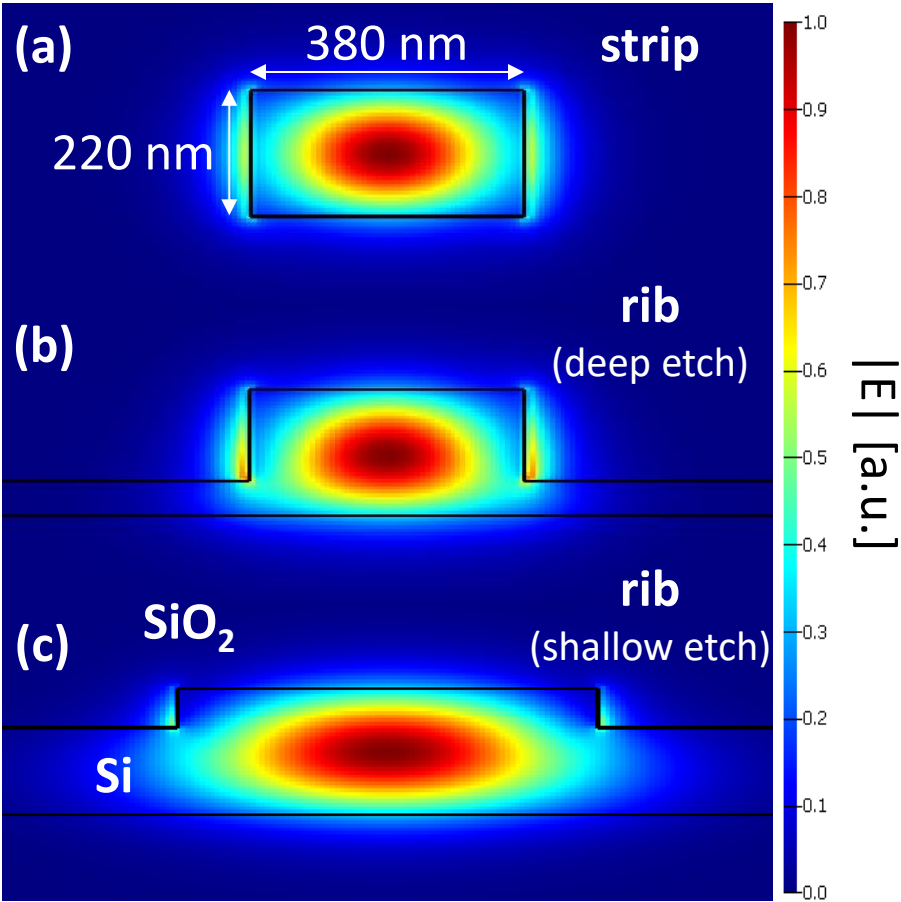


Vertical coupler



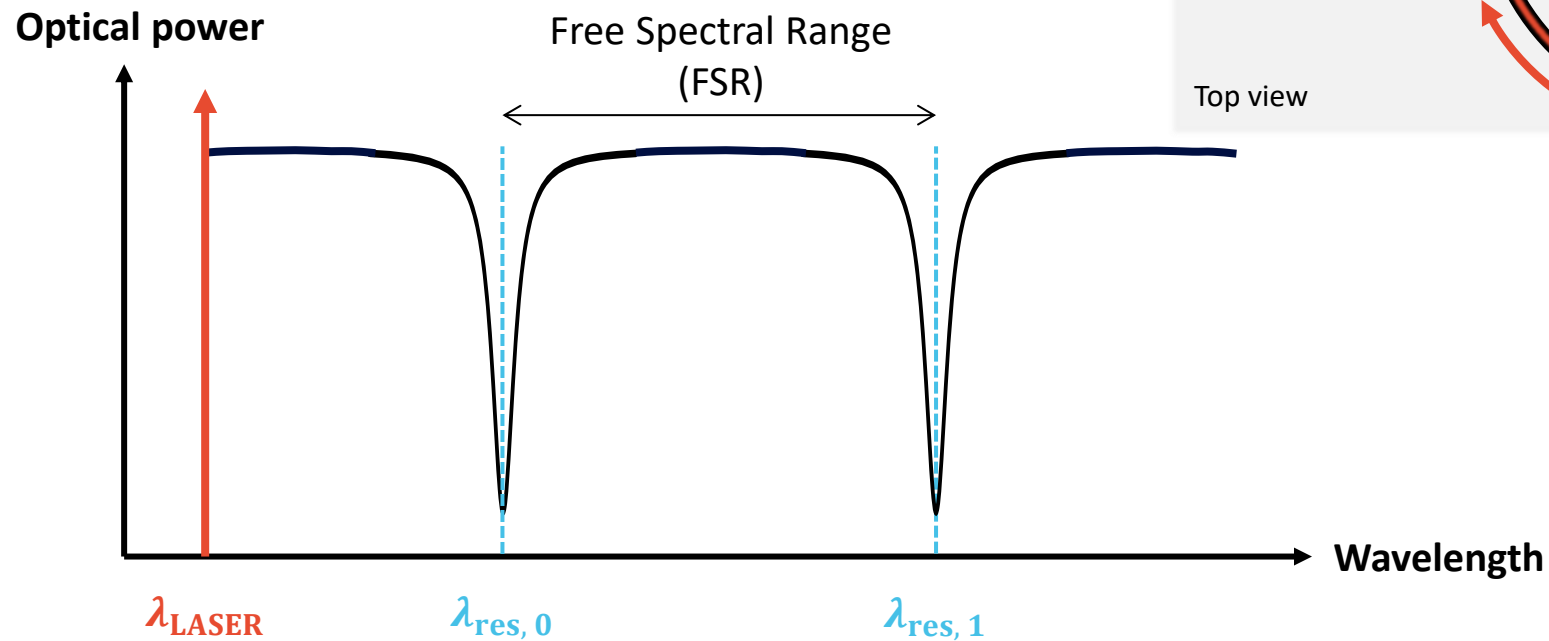
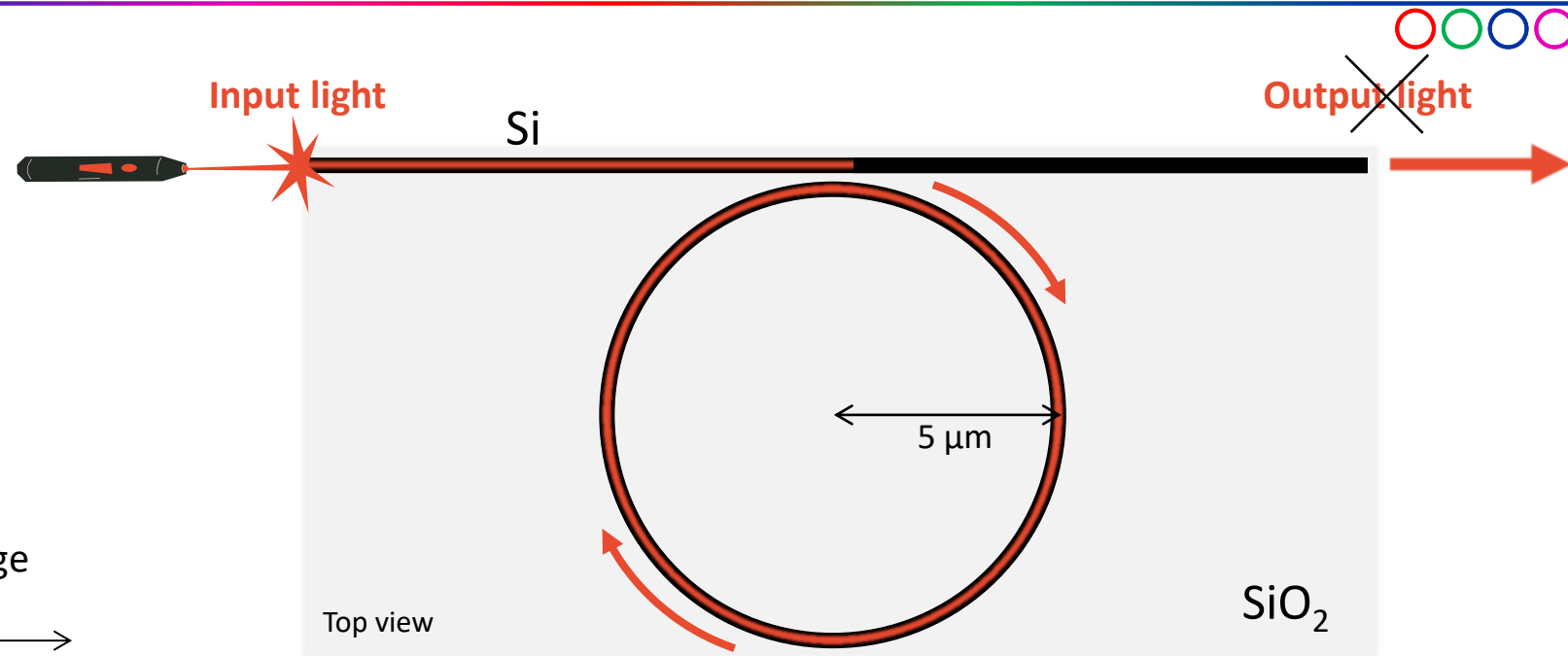
	Edge	Vertical
Insertion Loss	✓	✗
Bandwidth	✓	✗
Packaging Complexity	○	✓
Wafer Level Probing	○	✓

Waveguides cross-section



Working principle:

- Light coupled into the silicon micro-ring
- Destructive interference → **resonance**



$$\lambda_{\text{res}, m} = \frac{n_{\text{eff}} L}{m}, \quad m = 1, 2, 3, \dots$$

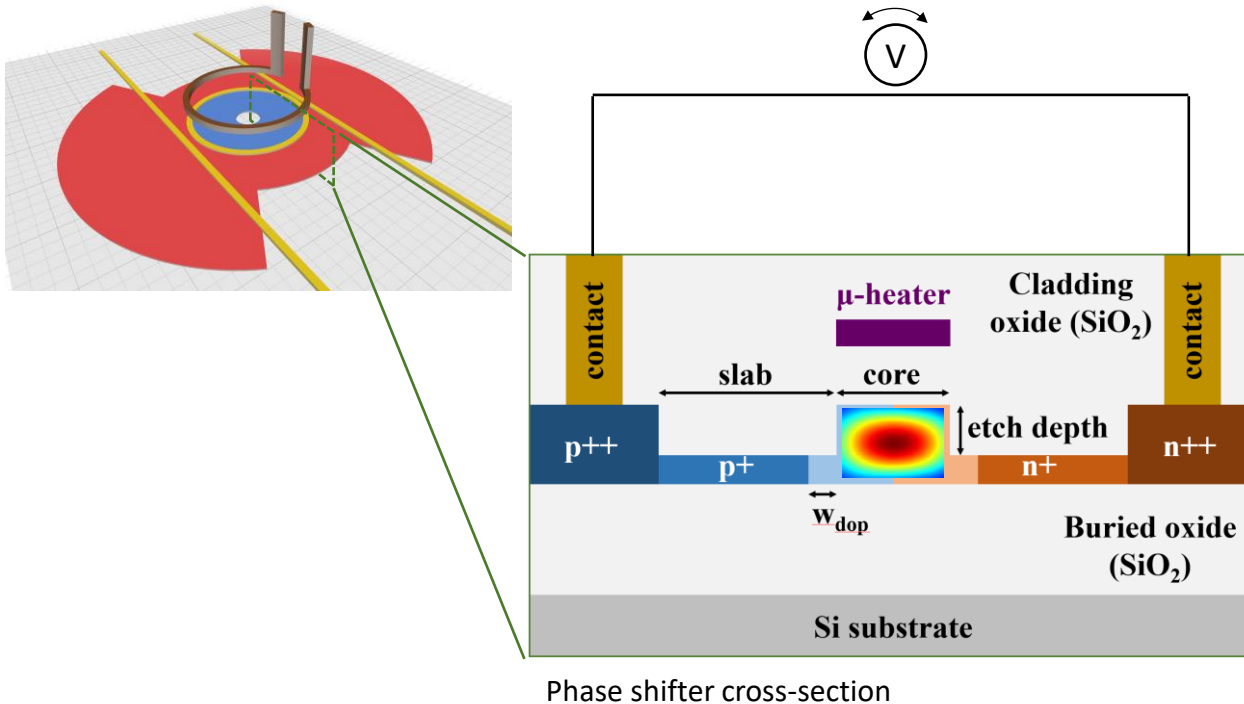
n_{eff} : effective refractive index
 L : round trip length

How do we modulate it?

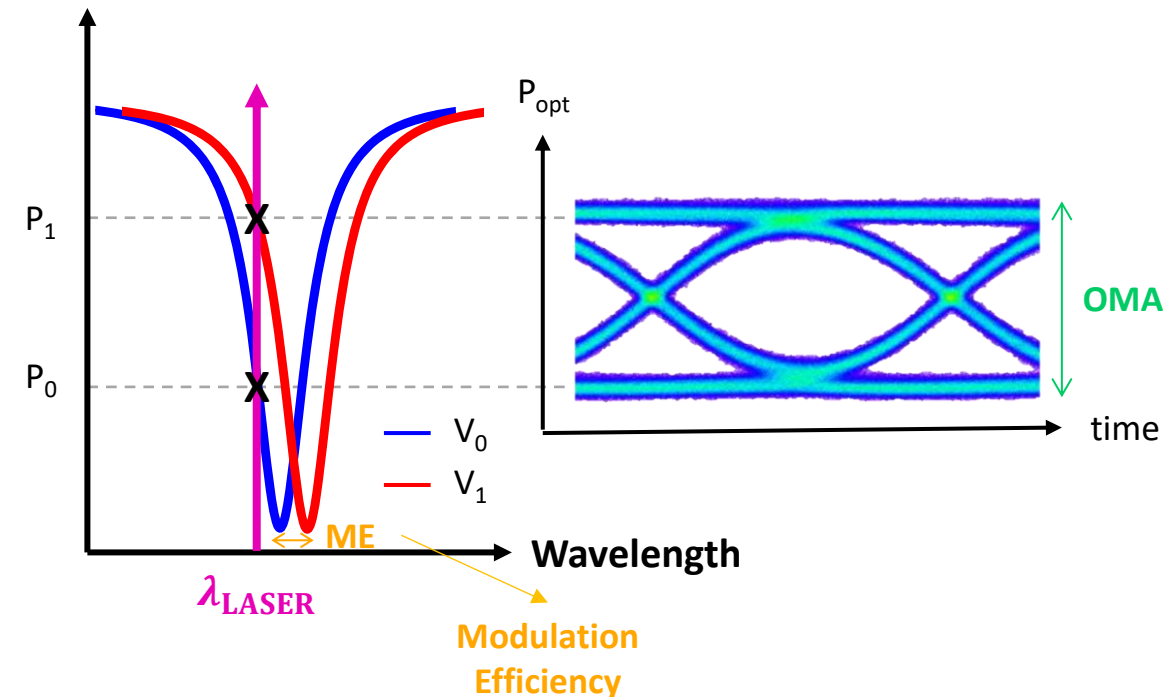
- Modulation of the resonance peak through the applied voltage
 - **Injection/depletion of carriers** → variation of the effective refractive index

$$\Delta n \propto -(\Delta N_{\text{electrons}} + \Delta N_{\text{holes}})$$

$$\Delta \alpha \propto (\Delta N_{\text{electrons}} + \Delta N_{\text{holes}})$$



Optical power

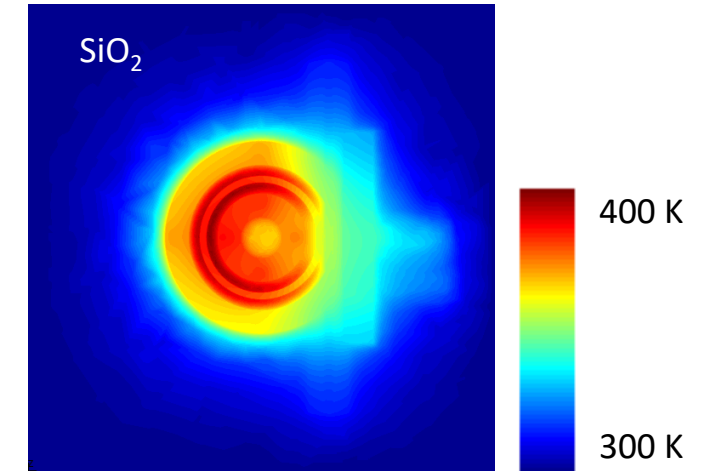
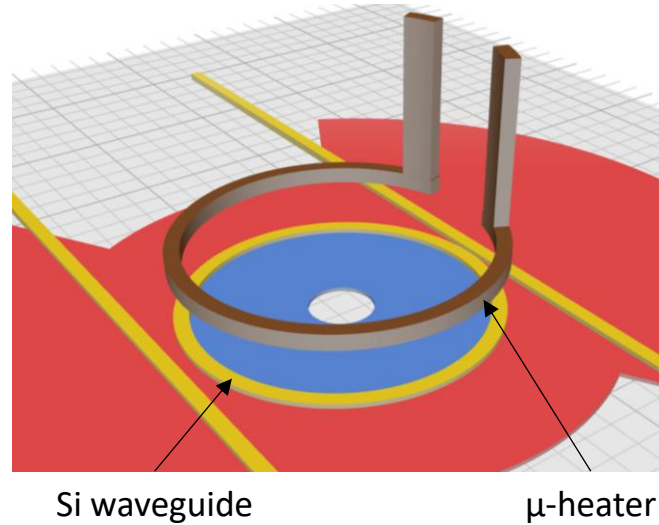
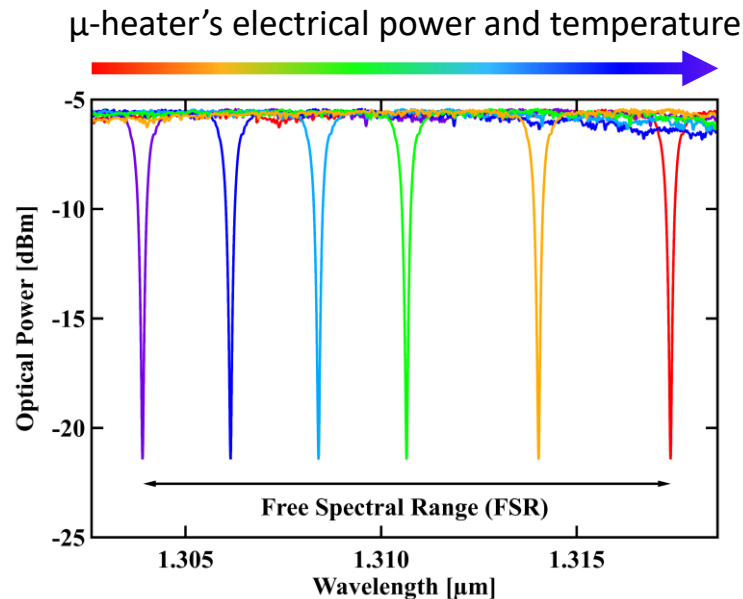


OMA: Optical Modulation Amplitude

ME: Modulation Efficiency



- Tungsten μ -heater to shift the resonance wavelength
- **Localized heating**
- Thermo-optic coefficient of silicon stronger than electrical modulation but **slower**



- Thermal shift coefficient of **70 pm/°C** for O-band (1310 nm) and **80 pm/°C** for C-band (1550 nm) ring modulators, significantly larger than the modulation efficiency (~ 35 pm/V)
- μ -heaters can be used for **localized thermal annealing**

Ring Modulators

X-ray irradiation tests



Static Test

Total ionizing dose

(TID) reached:

$12.3 \text{ MGy (SiO}_2\text{)}$

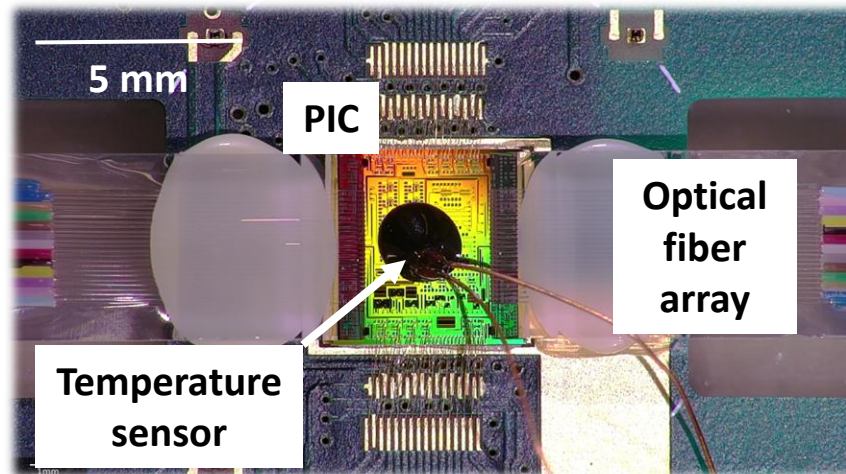
Irradiation time:

$\sim 9 \text{ days}$

Dose rate:

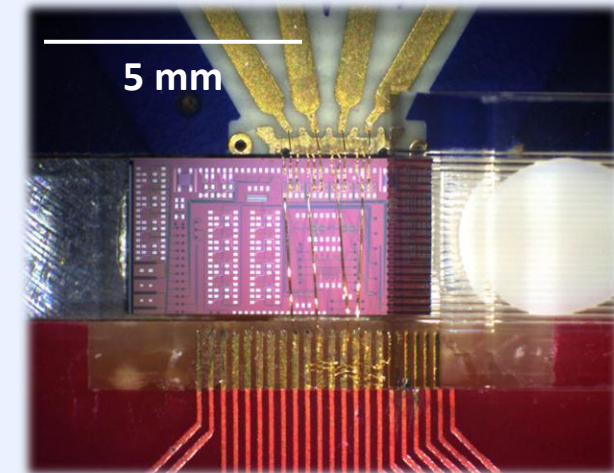
$\sim 55 \text{ kGy/h (SiO}_2\text{)}$

- Characterization of ring modulators and photodiodes under ionizing radiation
- Online acquisition of electrical (I-V) and optical (spectra) device parameters
- Investigation of temperature effects and thermal annealing post-irradiation

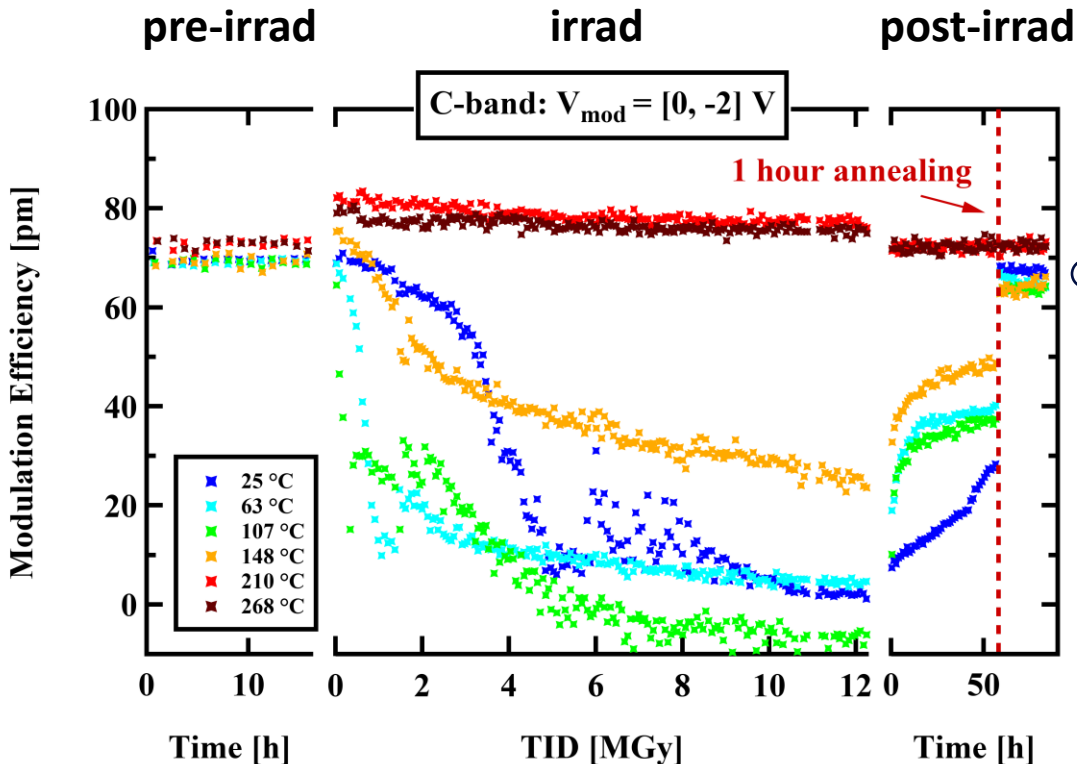


Dynamic Test

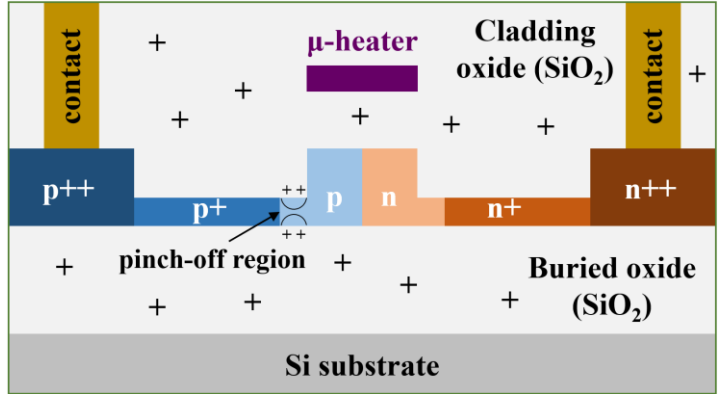
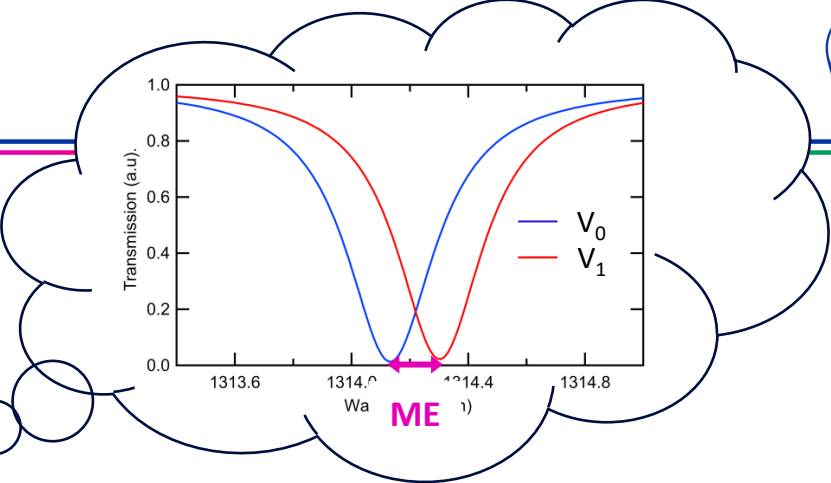
- Measurement of **electro-optic (EO) frequency response** of ring modulators under **ionizing radiation**
- Analysis across **different temperatures** and in the **10 MHz - 25 GHz** frequency range
- Investigation of **thermal annealing** during and after irradiation



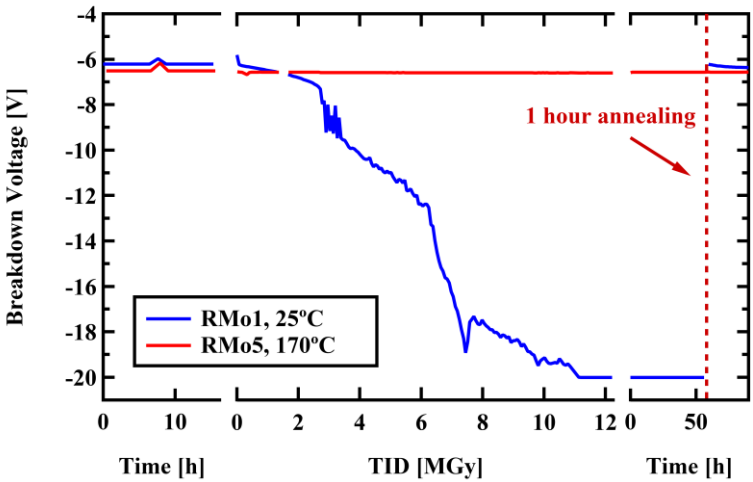
Static X-ray test – Results

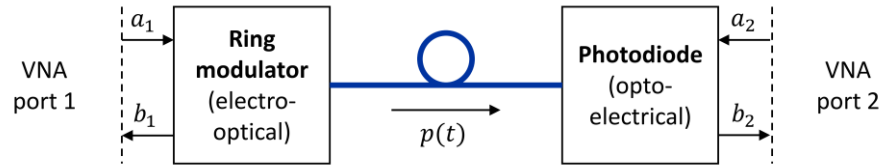


- Reduction in ME strongly dependent on temperature
- RMs at **intermediate temperature** range [50°C - 150°C] **degrades faster** than RM at room temperature
- ✓ One hour annealing at ~270°C effectively restores ME to pre-irrad values

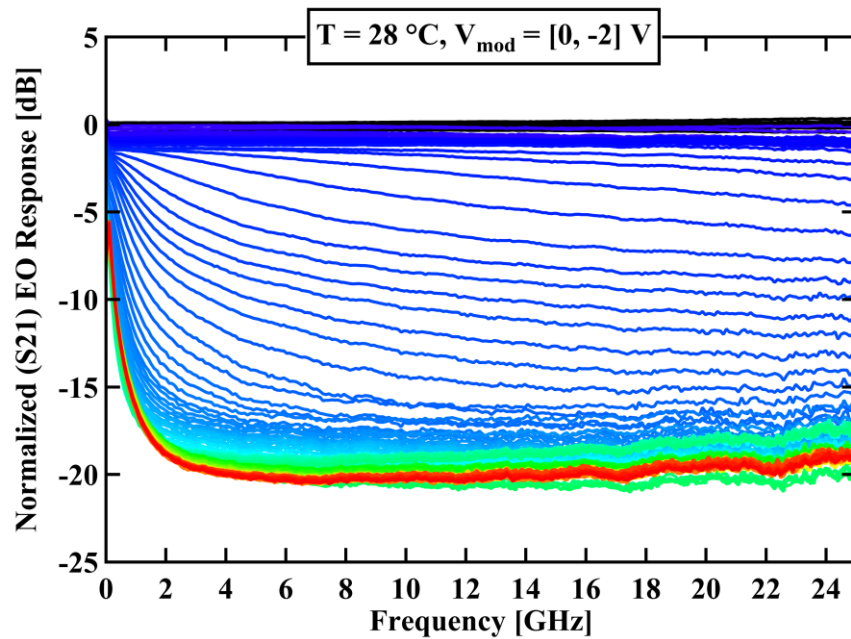


- Pinch-off of the p-slab caused by positive charge accumulation
- Increase in the breakdown voltage confirms the pinch-off mechanism

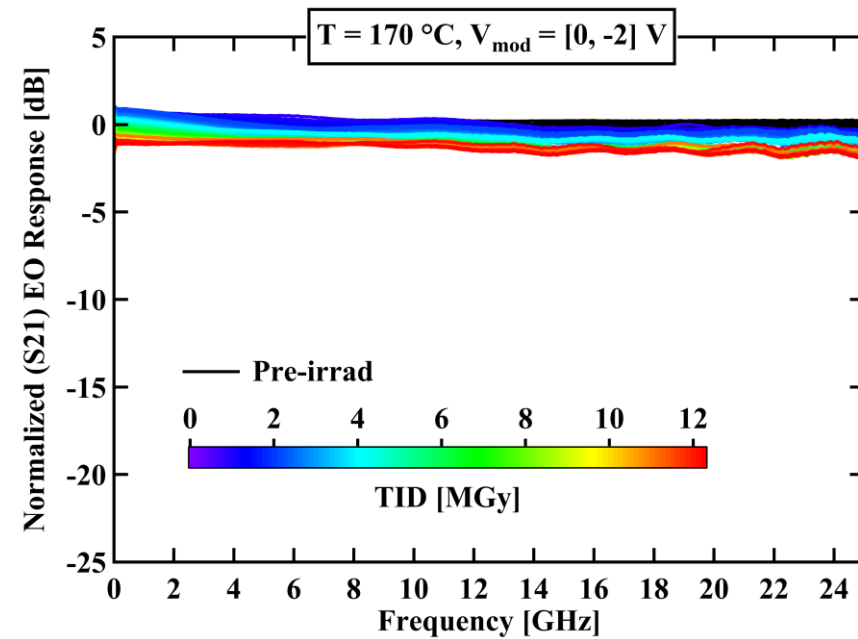




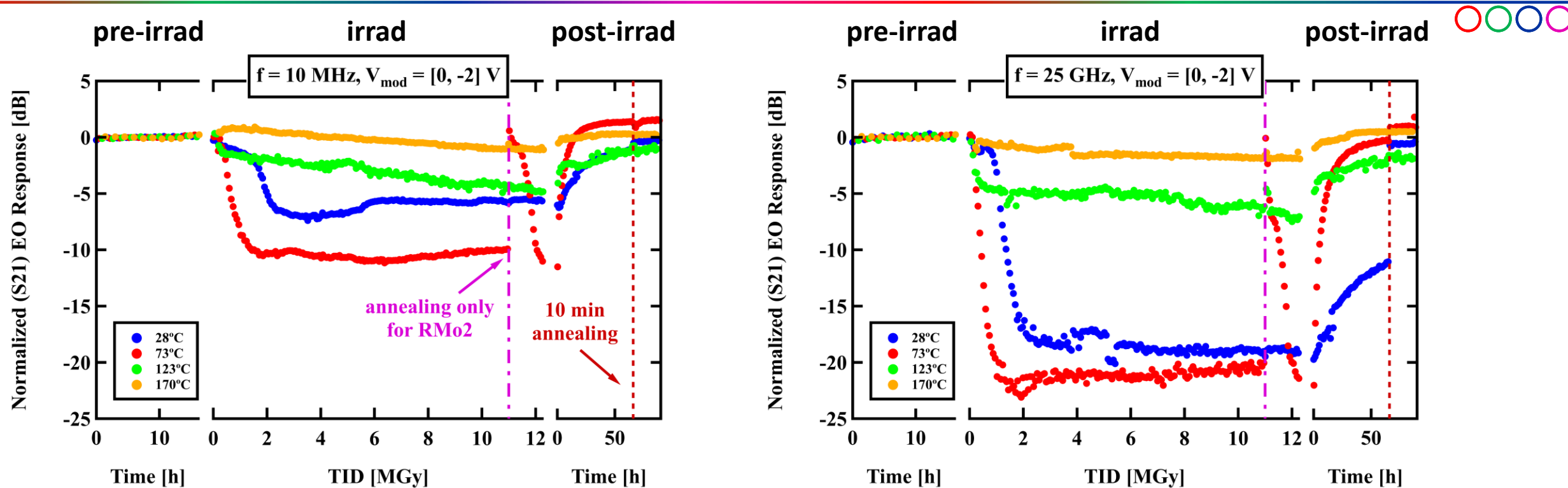
- EO frequency response (S21) measured online using a VNA (Vector Network Analyzer) and a high-speed photodiode



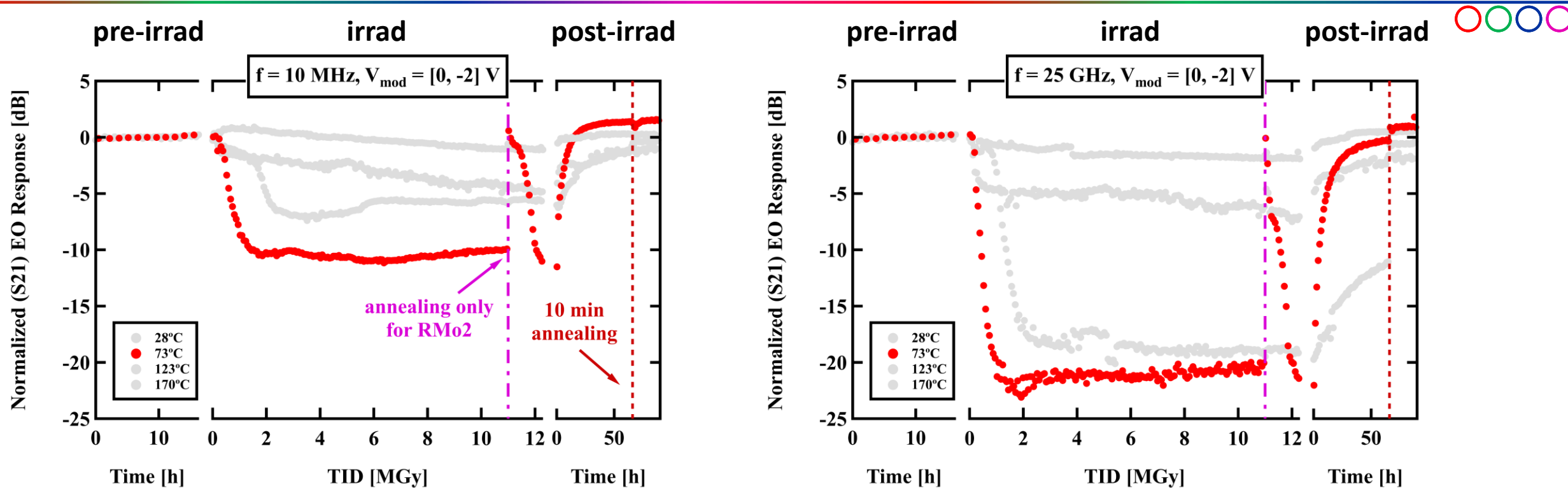
- TID damage is **frequency dependent** and **saturates** around 2 MGy for room temperature device



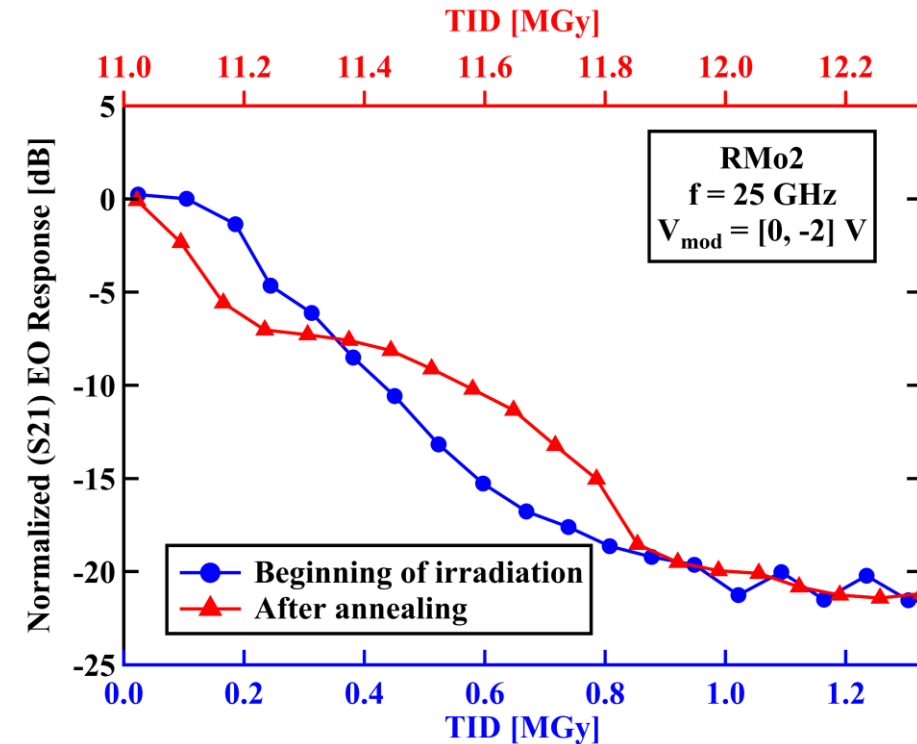
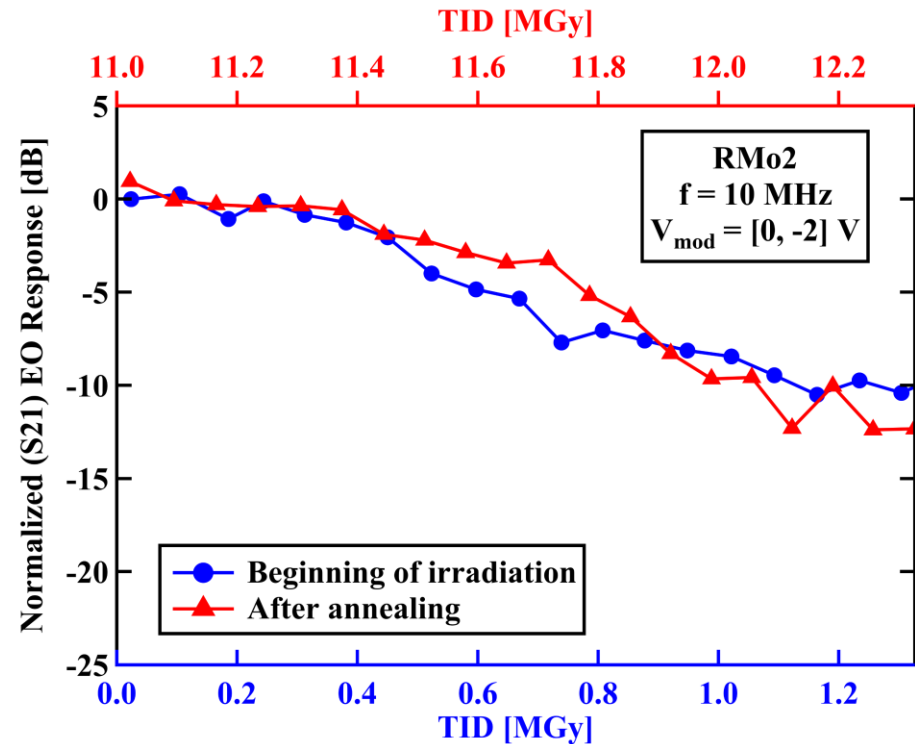
- RM at **170°C** thanks to the μ -heater **continuously anneal** TID damage



- S21 measurements are consistent with ME results from the static X-ray test:
 - **Faster degradation** observed in the **intermediate temperature** range compared to room temperature device
 - After irradiation, tried **shorter annealing** than in previous test: **10 minutes at 230°C** sufficient to recover the EO frequency response



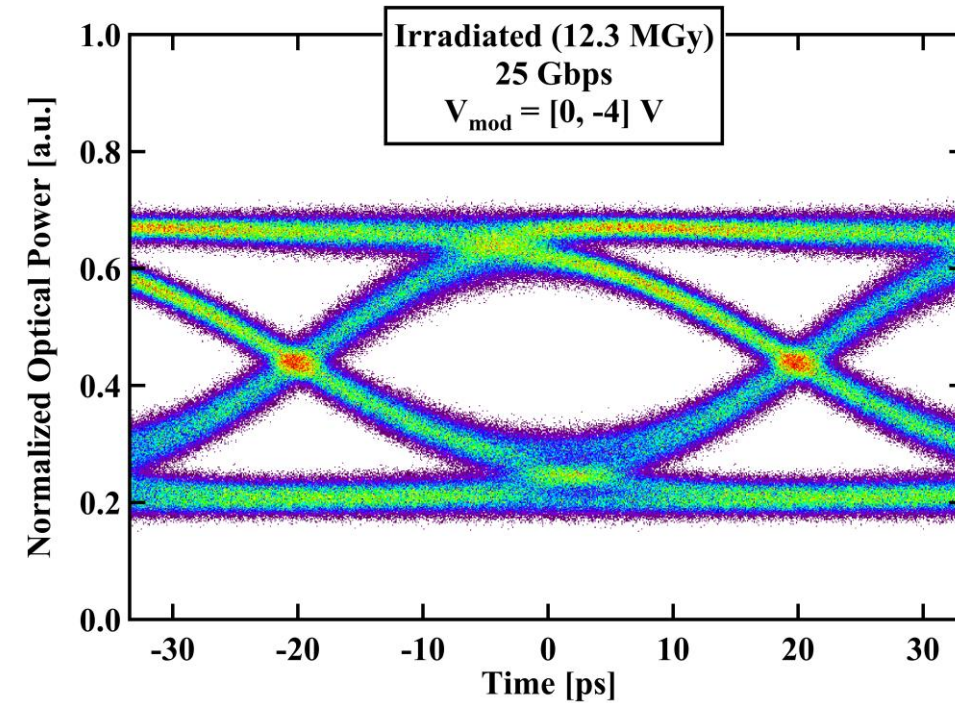
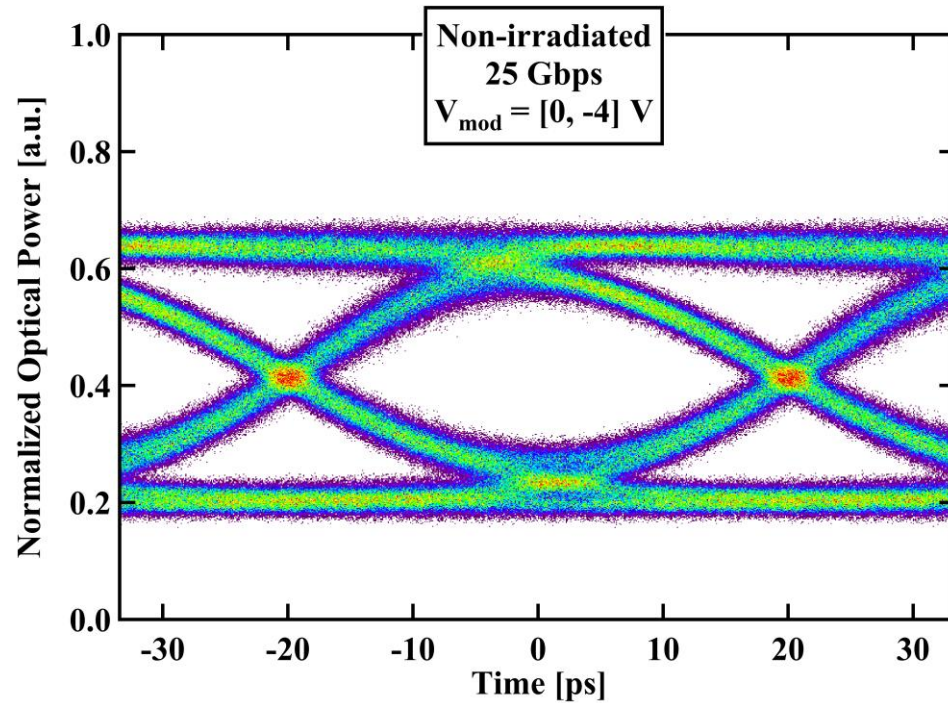
- After reaching the TID target of 10 MGy, a **thermal annealing** step was performed **only** for RMo2 **while keeping irradiating**
- RMo2 (only) kept at **230°C** for **approximately 30 minutes**, while measurement loop was continuing for other devices
- After the annealing step, **the temperature was lowered back** to 73°C



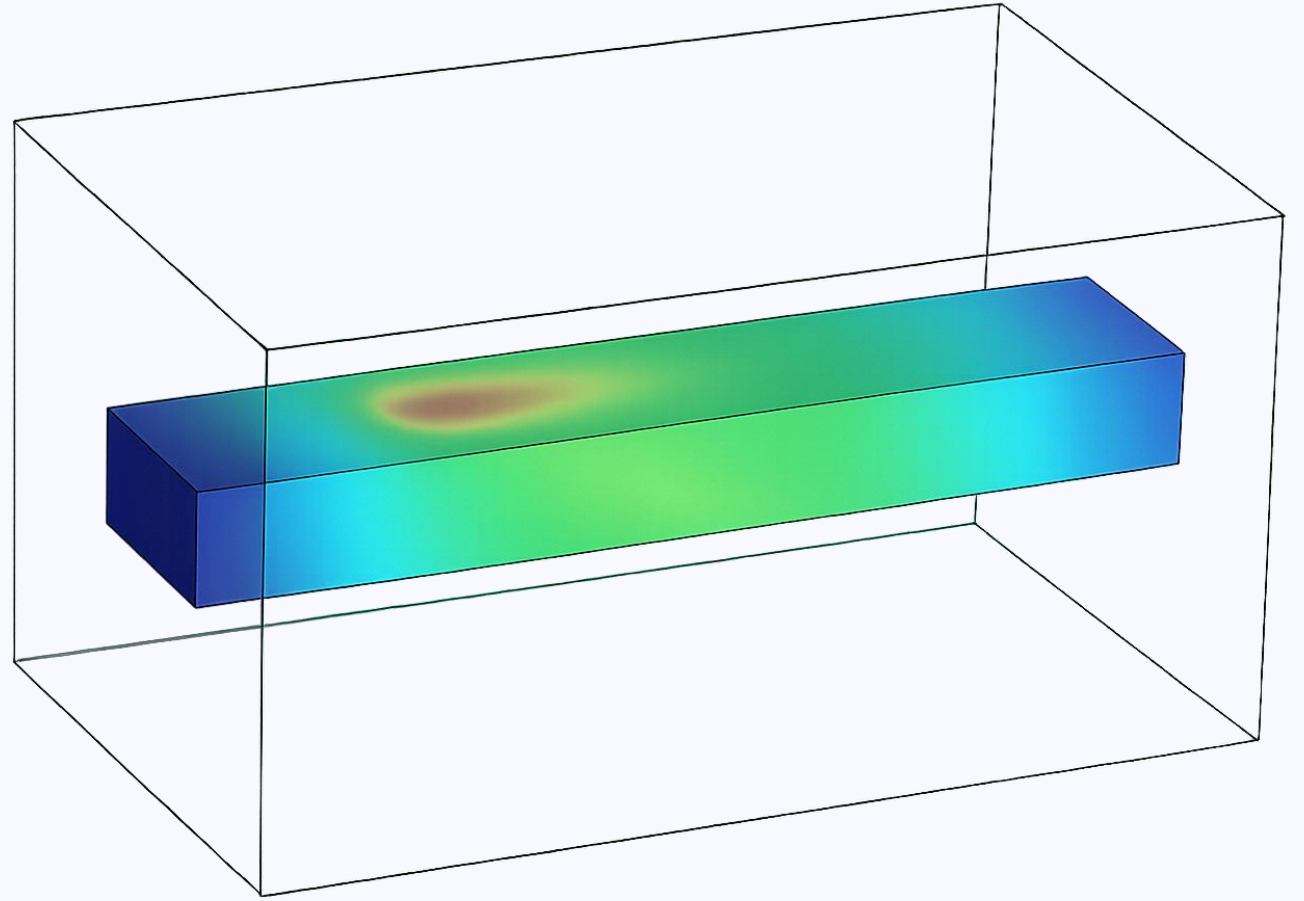
- TID damage resumes following almost the **same degradation trend** as observed at the beginning of the irradiation
- ✓ After localized thermal annealing, **radiation damage does not accumulate** with previous one



- Eye diagrams at 25 Gbps were acquired from the irradiated sample and compared with those from non-irradiated devices



- ✓ **No evidence of degradation** after thermal annealing
- ✓ Eye diagram parameters do not show differences compared to non-irradiated ring modulators

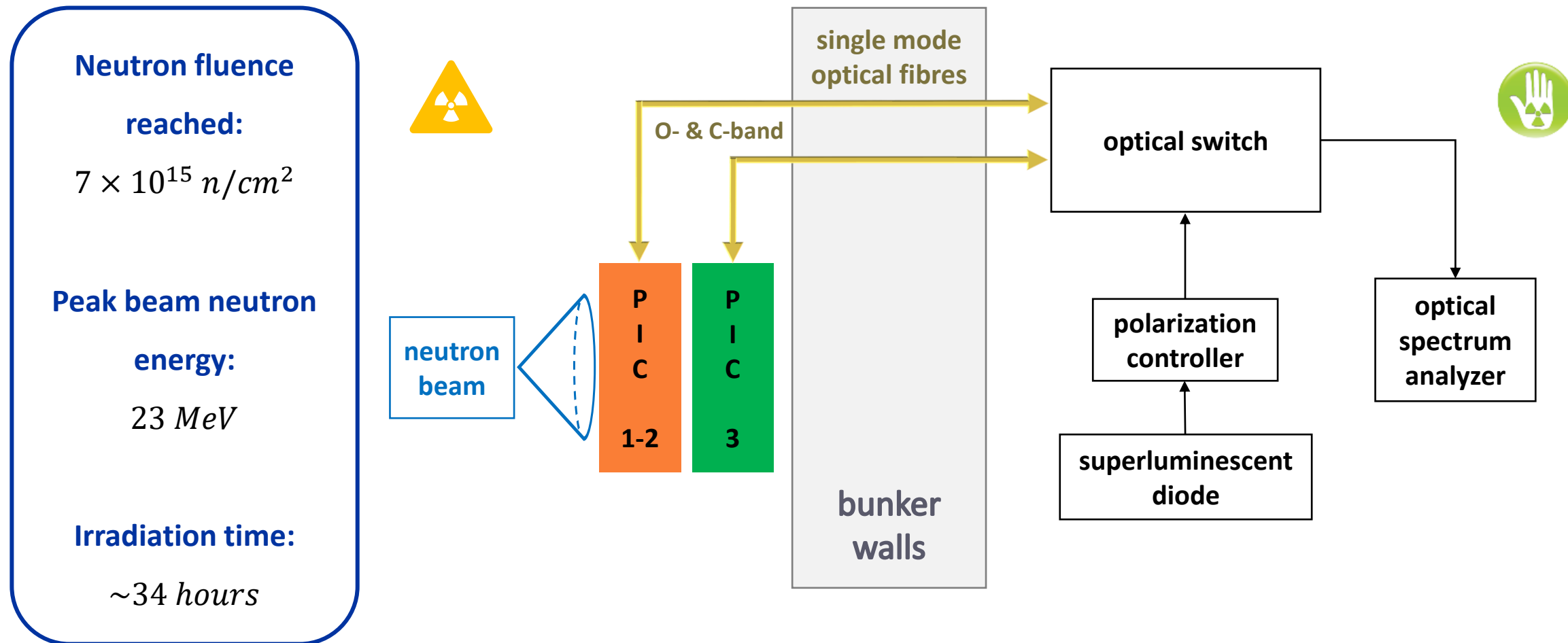


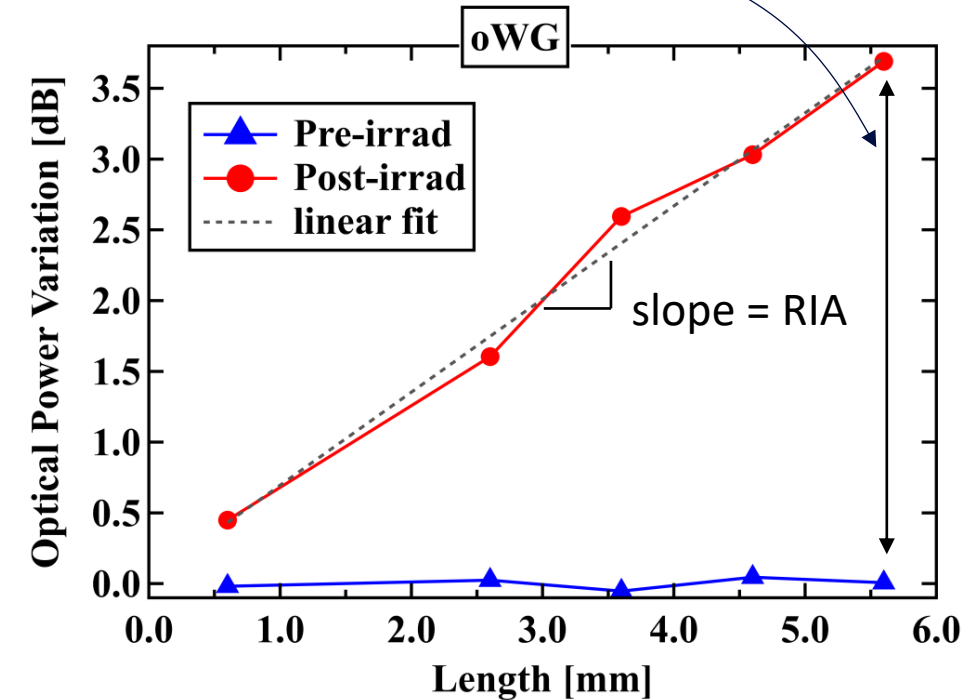
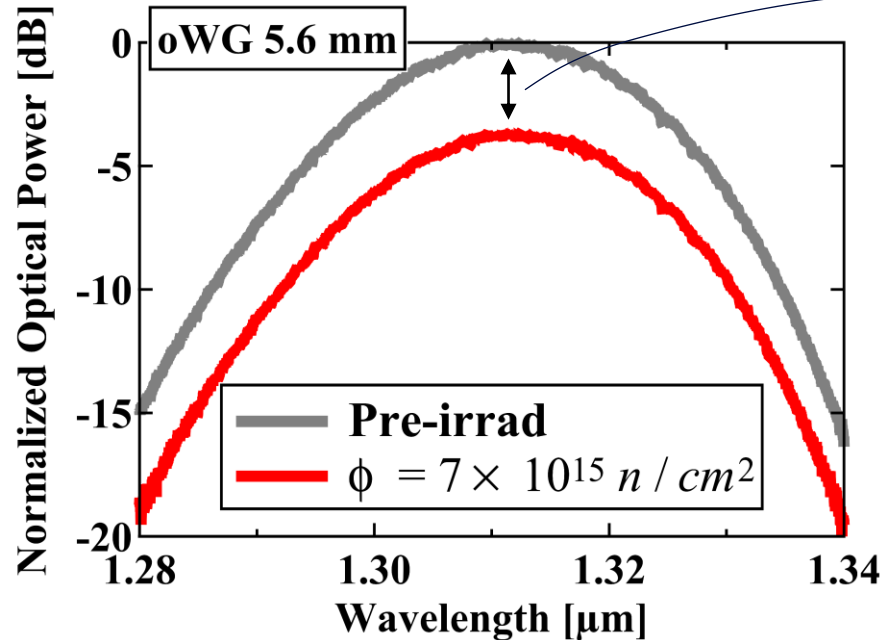
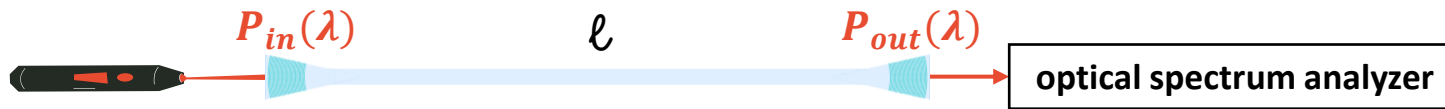
Waveguides

Irradiation campaigns and TCAD simulations

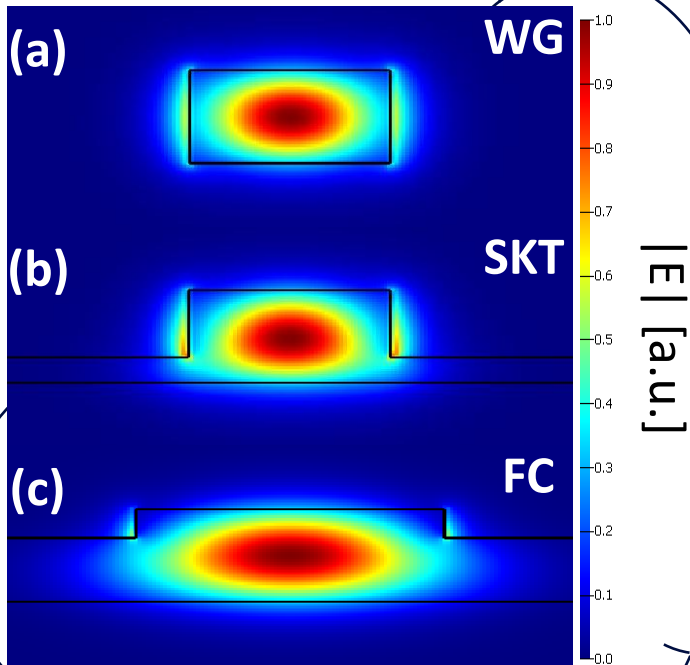


- Evaluation of **radiation-induced attenuation (RIA)** in SiPh waveguides
- Measurements of different waveguide types in the two optical bands (O-band at 1310 nm and C-band at 1550 nm)

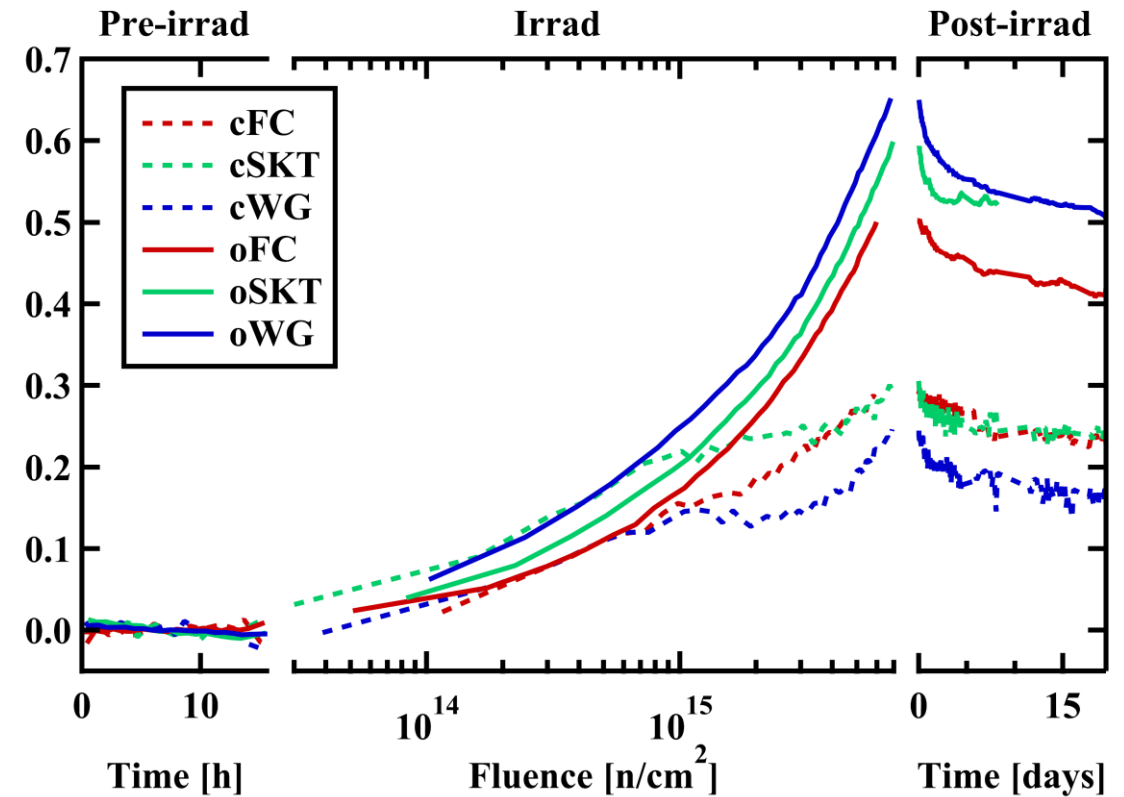




- Linear fit for the calculation of the RIA ('cut-back' method)
- The **variation of the slope** gives the **RIA**
- The variation of the y-intercept gives the variation in the grating coupler response (if any)



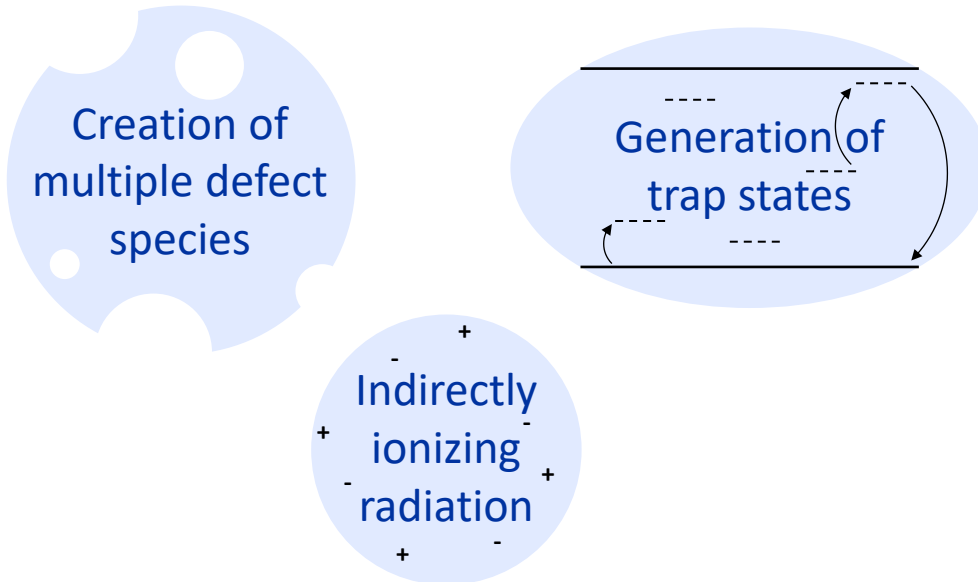
Radiation-Induced Attenuation (RIA) [dB/mm]



- Waveguides in O-band show a higher RIA than their counterpart in the C-band
- Attention must be taken when designing a PIC



- Displacement damage (DD)

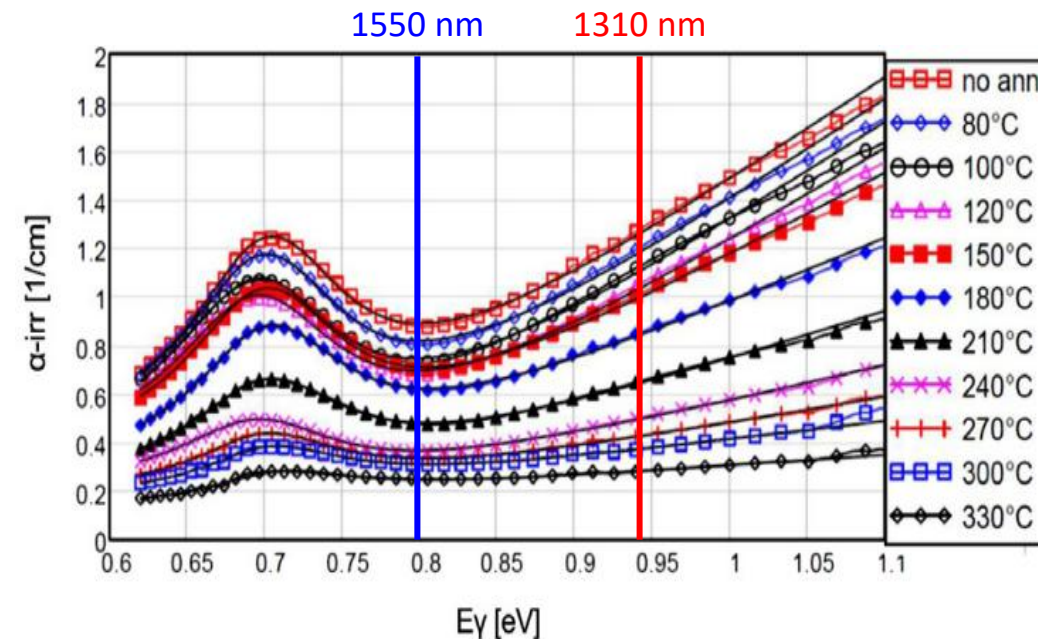


- Both studies show a larger increase in the absorption coefficient at **1310 nm** compared to **1550 nm**

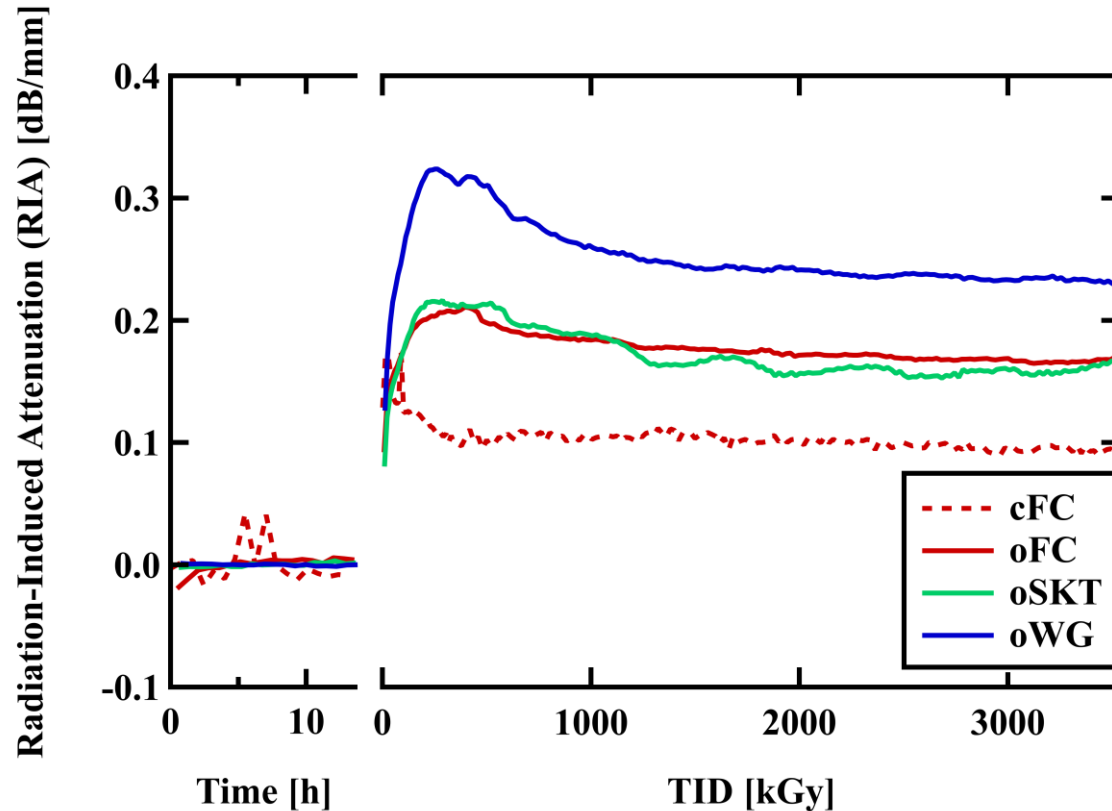
$$E|_{ev} = \frac{1.24}{\lambda|_{\mu m}}$$

- Defected-induced energy states reduce the optical absorption length

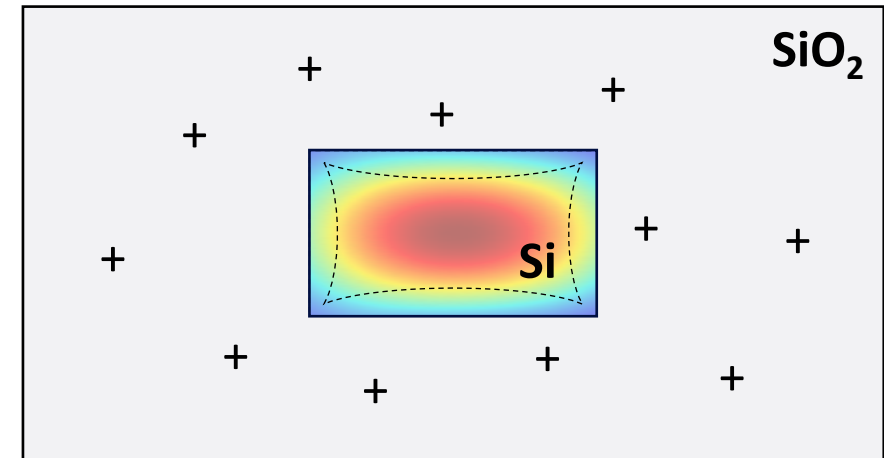
C. Scharf, F. Feindt, and R. Klanner, "Influence of radiation damage on the absorption of near-infrared light in silicon," *Nuclear Instruments and Methods in Physics Research Section A: Accelerators, Spectrometers, Detectors and Associated Equipment*, vol. 968, p. 163955, 2020. [Online]. Available: <https://www.sciencedirect.com/science/article/pii/S0168900220304277>



E. Fretwurst, R. Klanner, J. Schwandt, and A. Vauth, "Study of the v20 state in neutron-irradiated silicon using photon-absorption measurements," *Nuclear Instruments and Methods in Physics Research Section A: Accelerators, Spectrometers, Detectors and Associated Equipment*, vol. 1053, p. 168353, 2023. [Online]. Available: <https://www.sciencedirect.com/science/article/pii/S0168900223003431>



- Same setup as for the neutron test
- X-ray test to **decouple the RIA from non-ionizing and ionizing radiation**
- **RIA saturates**, confirming our previous measurements and some results found in literature



- Hypothesis: the accumulation of positive charges in the SiO₂ and at the Si/SiO₂ interface pushes free carriers in the waveguide (slightly p-doped) toward the center, increasing their **overlap with the optical mode** and enhancing absorption due to free-carrier absorption

Many thanks to [Carlos Solans Sanchez](#) and the [ATLAS Tracking Detectors \(EP-ATL-TRK\)](#) group for providing access to their X-ray facility, and to [Kourosh Sarbandi](#) for assistance with the dosimetry!



- Evaluation of **optical single-event transients (OSETs)** in SiPh waveguides
- **First heavy-ion test for OSETs** (no tests for OSETs have been reported in the literature)

Max. LET available from
the ion cocktail:

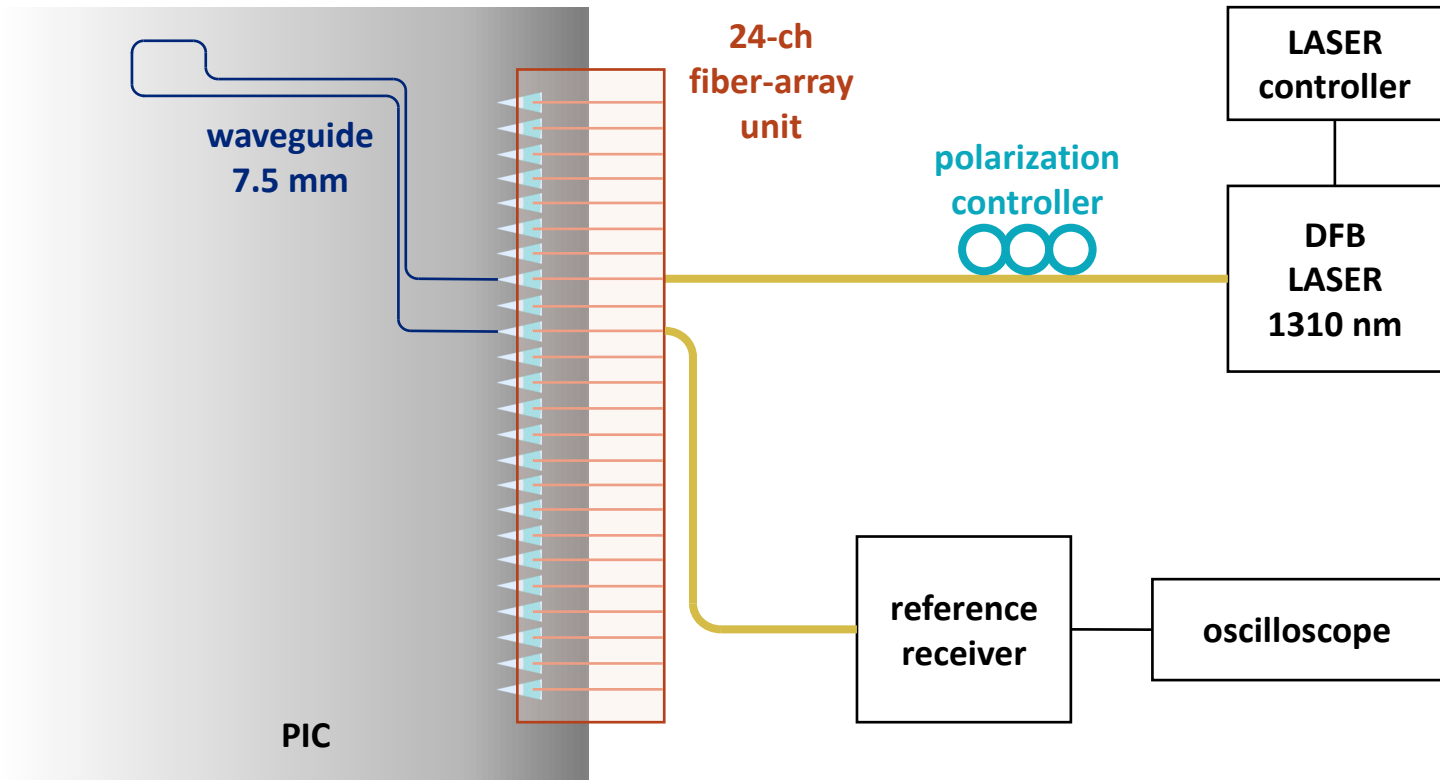
$$61.3 \text{ MeV} \cdot \text{cm}^2/\text{mg}$$

Ion flux:

$$15000 \text{ ions/s} \cdot \text{cm}^2$$

Angles of incidence:

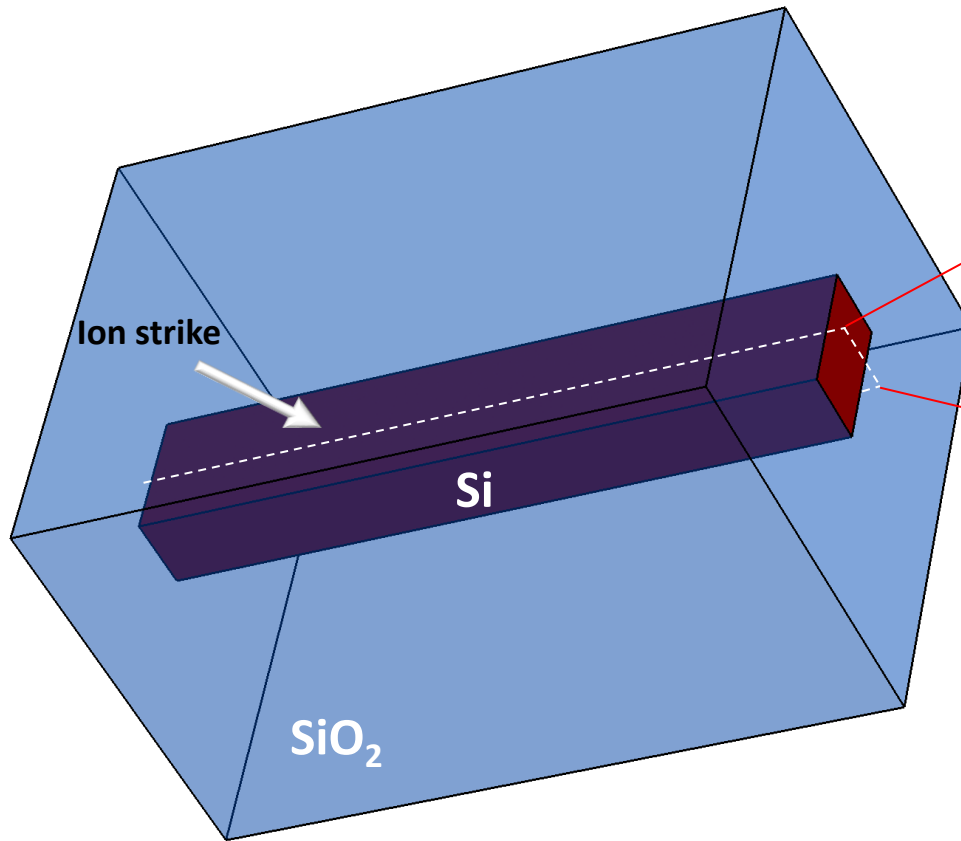
$$0^\circ - 45^\circ - 75^\circ$$



Heavy ion test – What is an OSET?

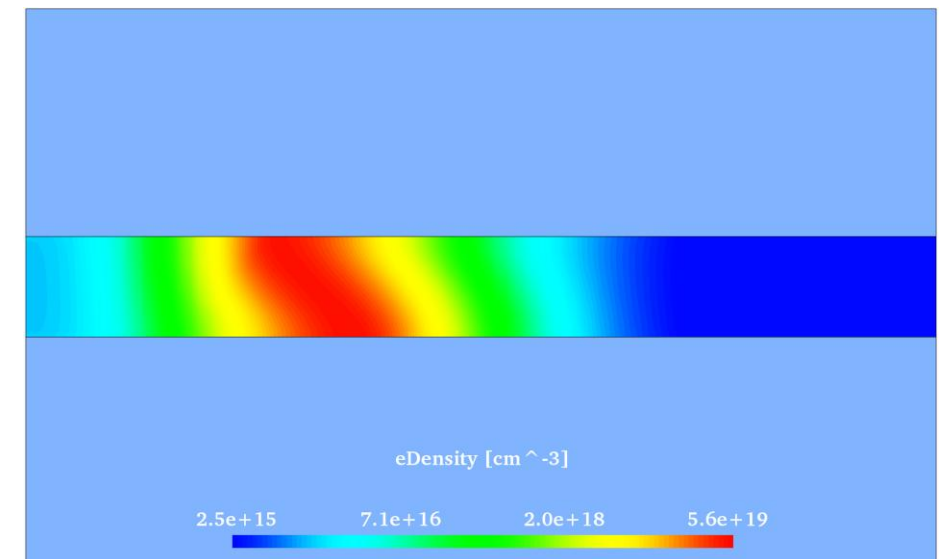
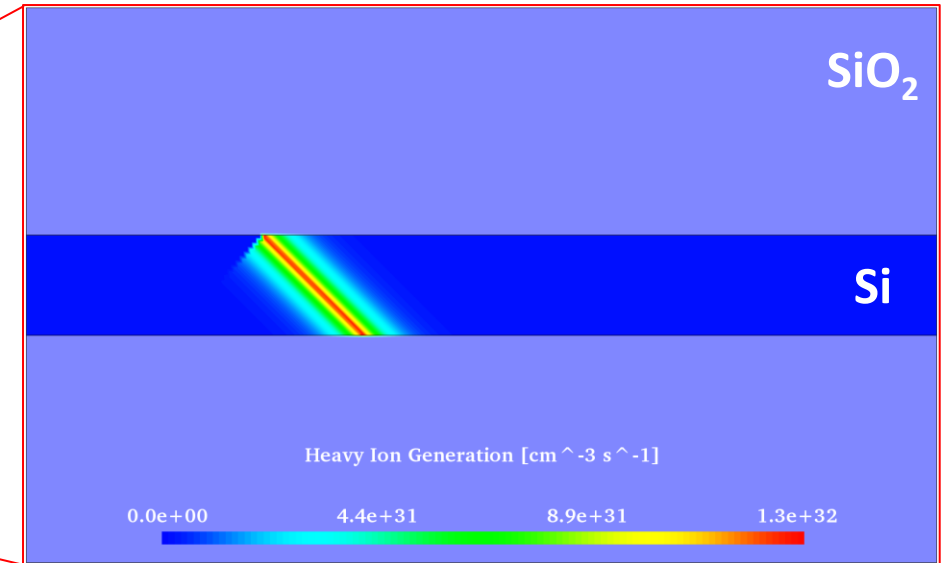


OSET: single-event transient in the optical domain



$$n(\lambda, N_e, N_h) = n_0(\lambda) + \Delta n_{fc}(N_e, N_h) - i \frac{\lambda}{4\pi} \Delta \alpha_{fc}(N_e, N_h)$$

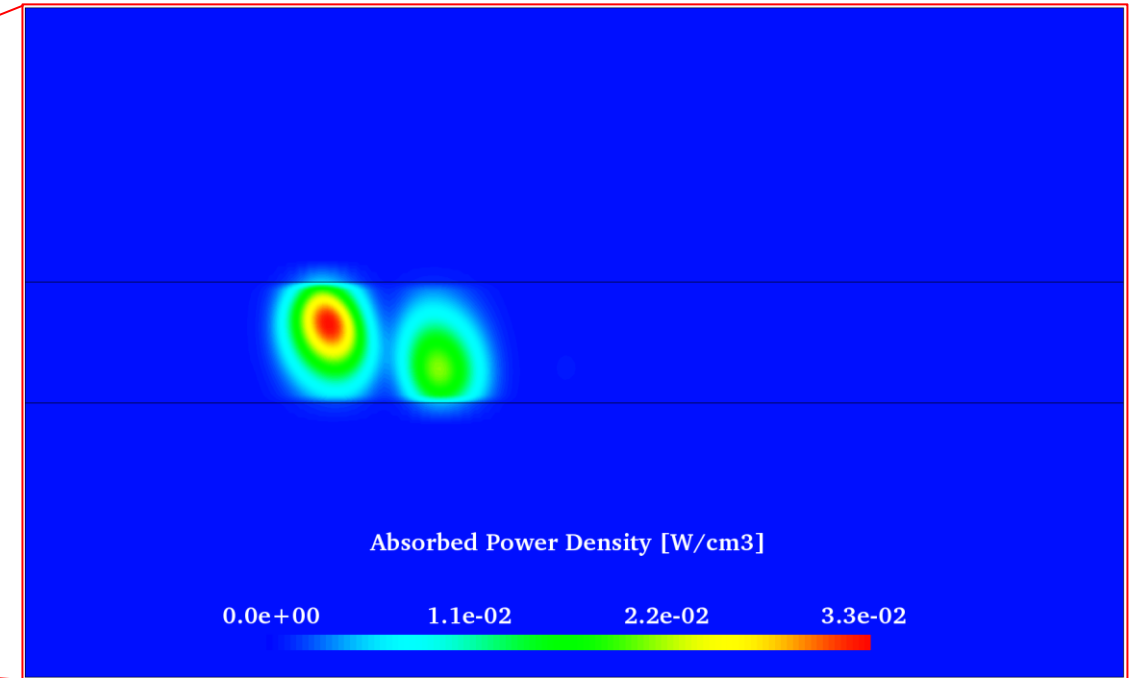
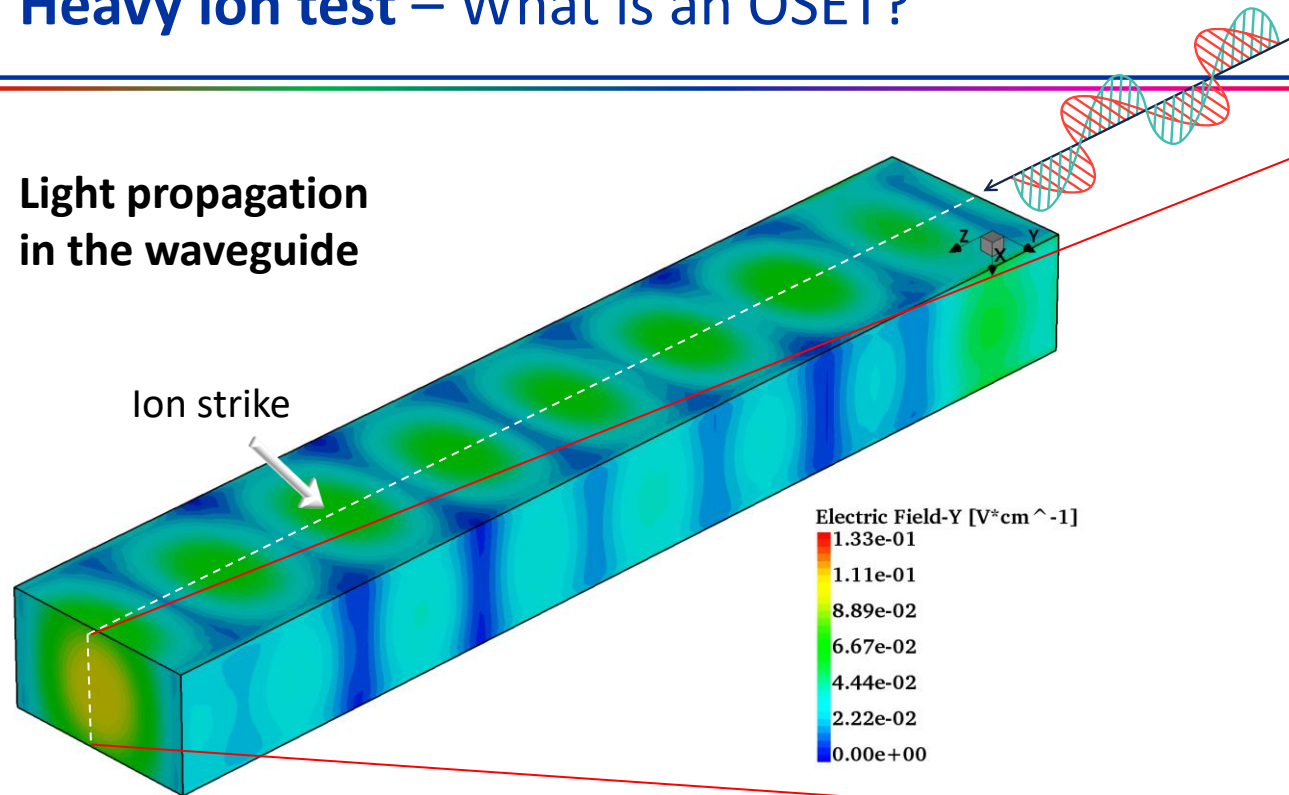
$$\text{absorption } (\Delta \alpha) \propto (\Delta N_{\text{electrons}} + \Delta N_{\text{holes}})$$



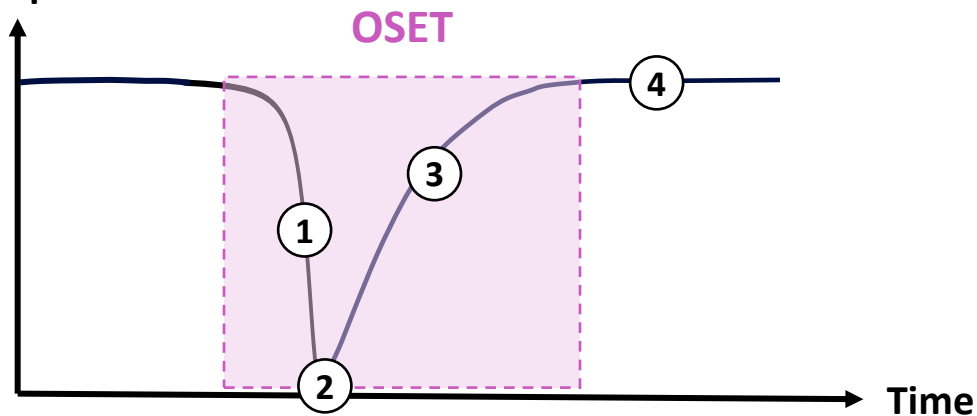
Heavy ion test – What is an OSET?



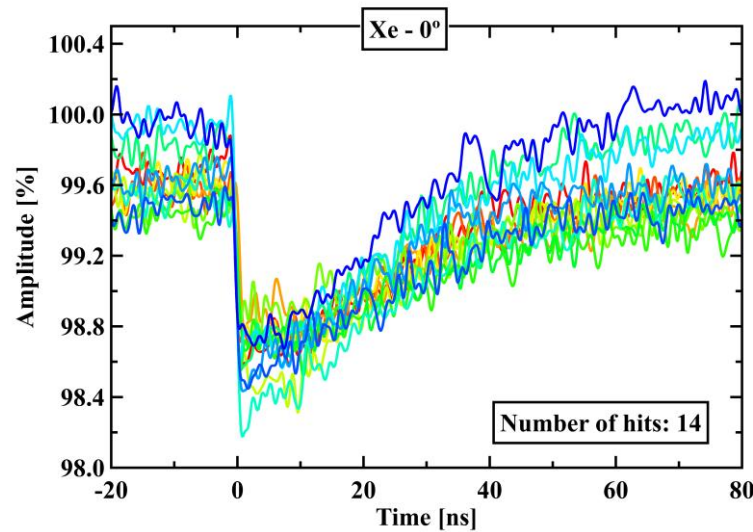
Light propagation
in the waveguide



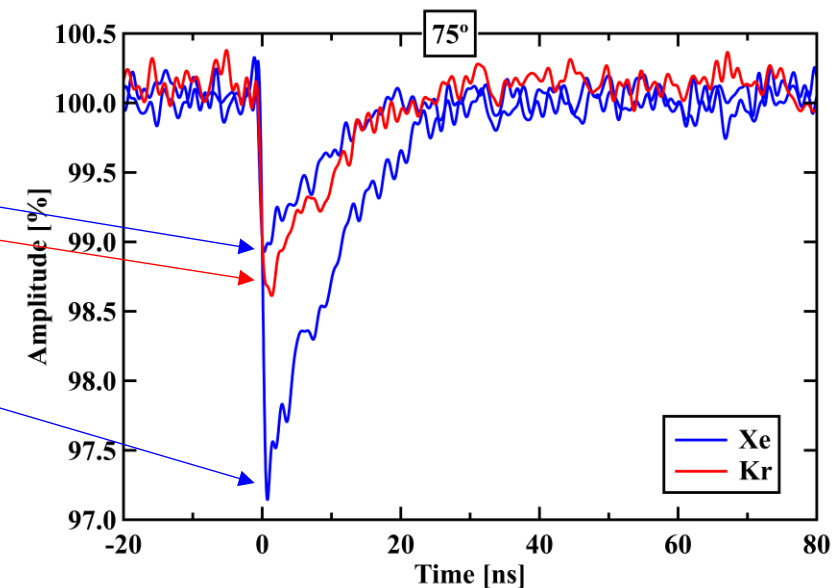
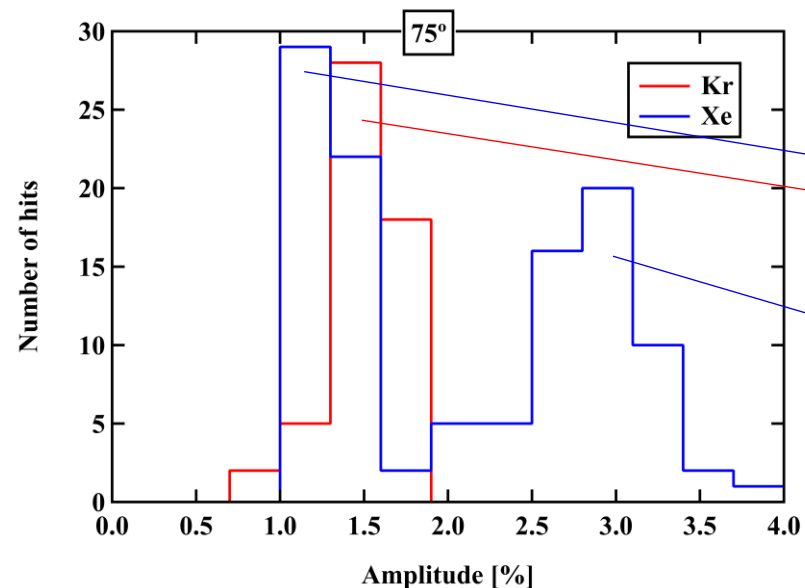
Output power



- ① Initial carrier generation from ion strike [100 ps to 1 ns]
- ② Peak of carrier generation and optical attenuation
- ③ Recombination mechanisms [tens of ns]
- ④ Complete recovery from the transient event [after ~100 ns]
(unit interval for a bit at 25 Gbps is 40 ps)

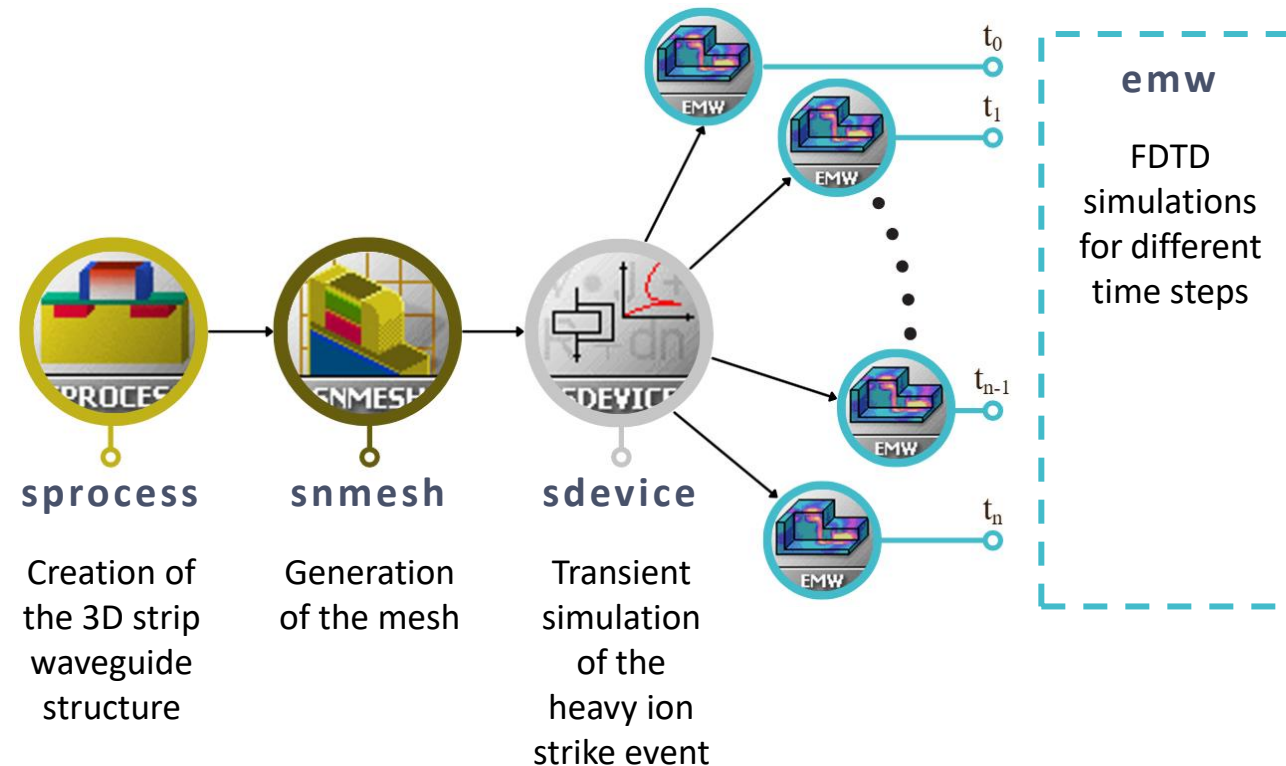


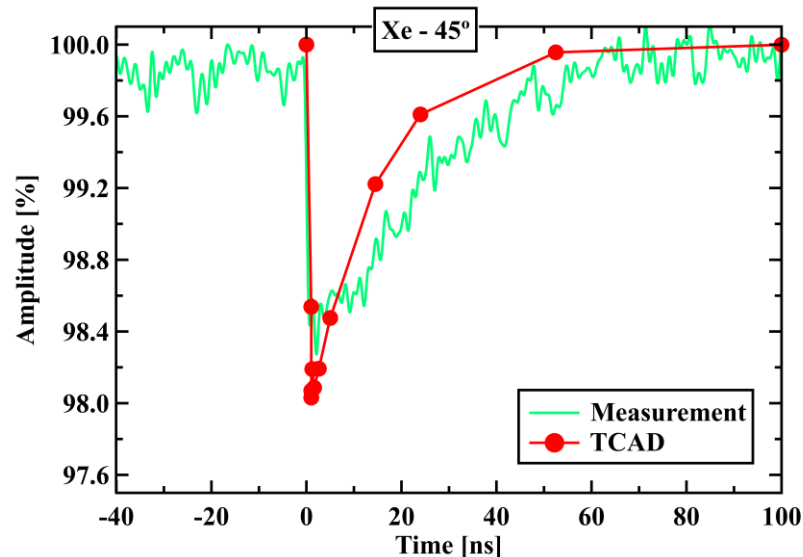
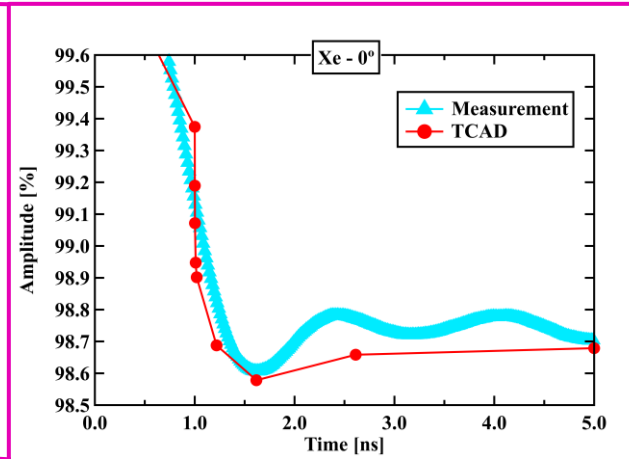
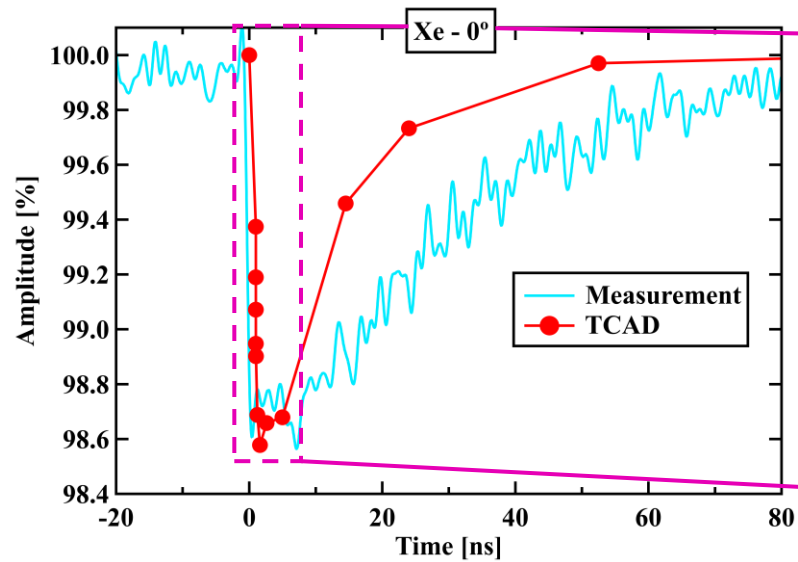
- For perpendicular strike, OSETs were observed only for the heaviest ion ($^{124}\text{Xe}^{35+}$, LET of $61.3 \text{ MeV}\cdot\text{cm}^2/\text{mg}$)
- The ratio was approximately of 1 hits/min, with maximum amplitude of transient of $\sim 1.5 \%$
- **Maximum transient amplitude of $\sim 4 \%$** with highest LET and angle of incidence of 75°
- Two-peaks distribution of the transient amplitude because of the L-shaped waveguide





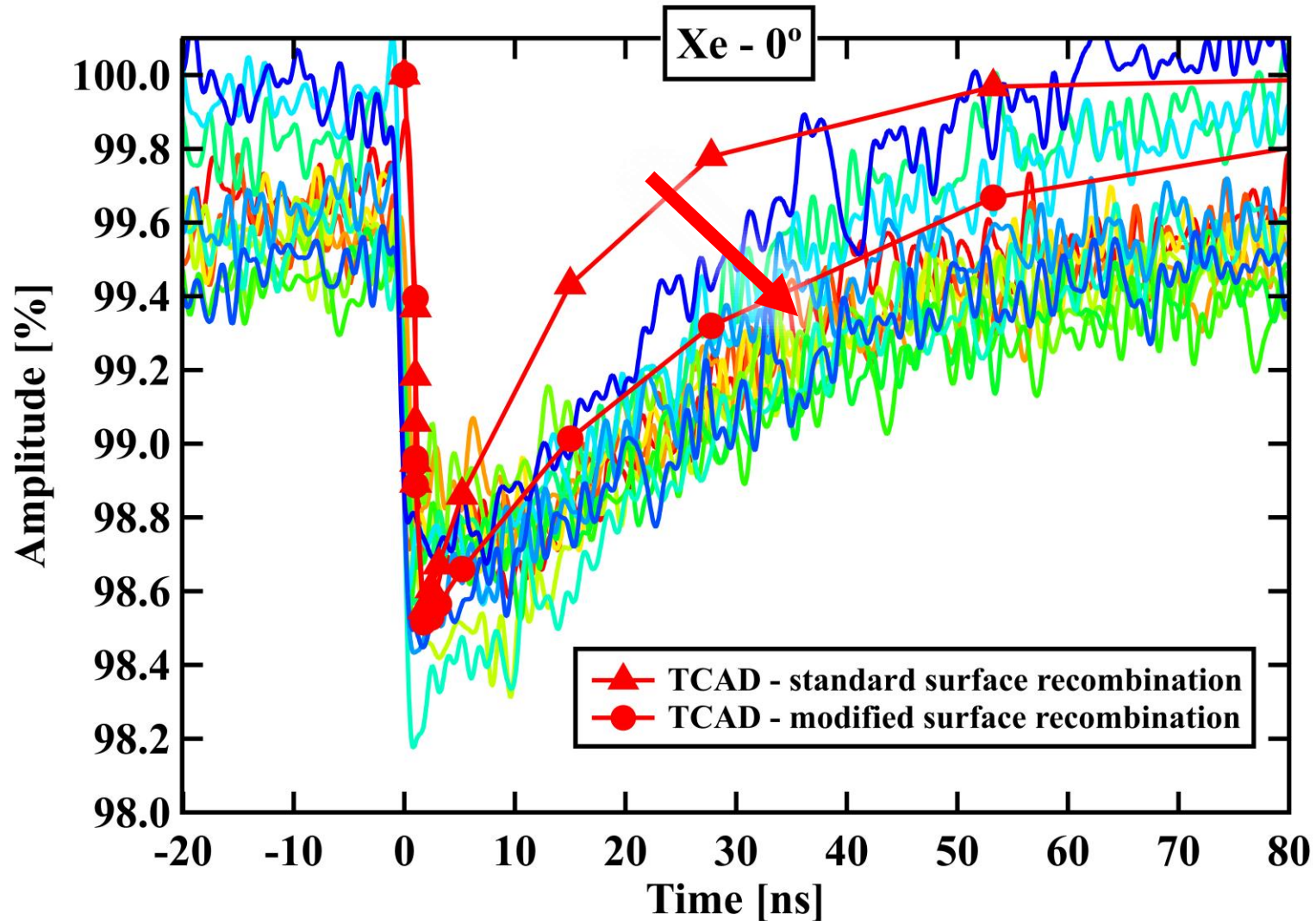
- Sentaurus TCAD is a powerful tool to combine:
 - **Electrical simulations** → carrier generation, diffusion and recombination from the heavy ion strike (**variation in the complex refractive index** due to the different number of carriers)
 - **Electromagnetic simulations** → finite-difference time-domain (**FDTD**) solver to compute the electromagnetic field propagation





- Starting from the LET of $61.3 \text{ MeV}\cdot\text{cm}^2/\text{mg}$ we can set a defined number of electron-hole pairs generated per volume within the TCAD simulation (details of the calculations in the backup)
- **Amplitude of the transient matches well the measurements**
- Good match also for the left-hand side of the transient (initial charge generation)

- The transient amplitude shows a **good matching also when the angle of incidence is changed**
- **Overestimation of the recombination time constant** (for now used the pre-defined TCAD values, trying with different recombination parameters)



$$s = s_0 \left[1 + s_{\text{ref}} \left(\frac{N_i}{N_{\text{ref}}} \right)^\gamma \right]$$

- By reducing the **surface recombination velocity** from the default value, we match not only the amplitude of the OSET but also the typical recovery time



- **Dynamic X-ray irradiation test** on SiPh **ring modulators** have demonstrated the susceptibility of the electro-optic frequency response to TID damage (pinch-off mechanism of the silicon slab).
- **Localized thermal annealing** using the built-in micro-heaters **restores completely the performance**. No sign of degradation in the eye diagrams after thermal annealing.
- **Neutron and X-ray irradiation tests** on SiPh **waveguides** highlighted evidence of **radiation-induced attenuation** that must be considered for future PIC designs.
- **Heavy ion** testing demonstrated **non-significant influence of OSETs** in the SiPh waveguides transmission. Transient amplitude with LET up to $61.3 \text{ MeV}\cdot\text{cm}^2/\text{mg}$ and angle of incidence of 75° remained **below 4 %**.
- **TCAD simulations of OSETs events** show a good agreement with the measured transient, both in amplitude and recombination time.

...and future work

- Write the thesis 🧐



Thank you for your attention!

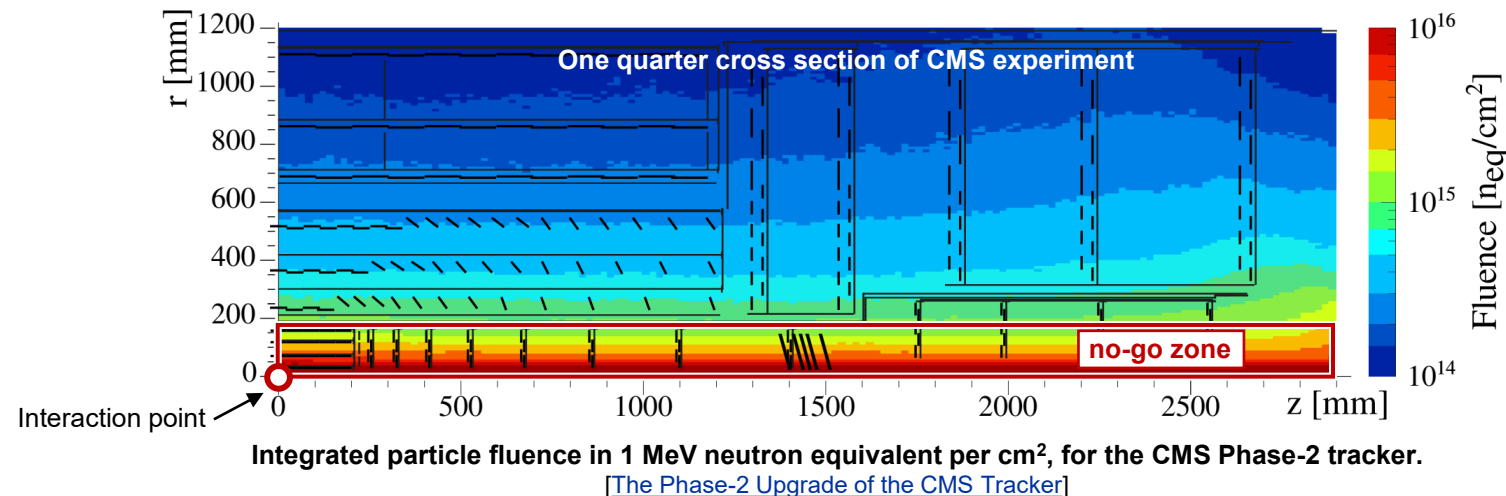


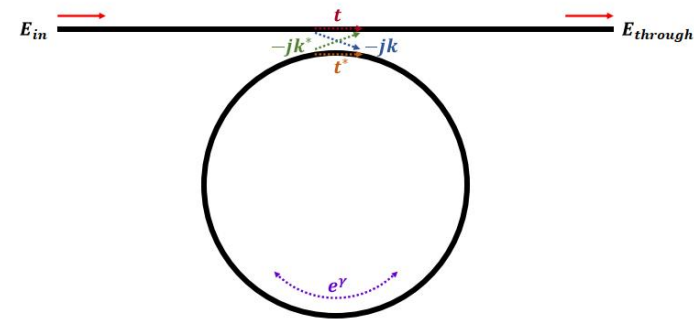




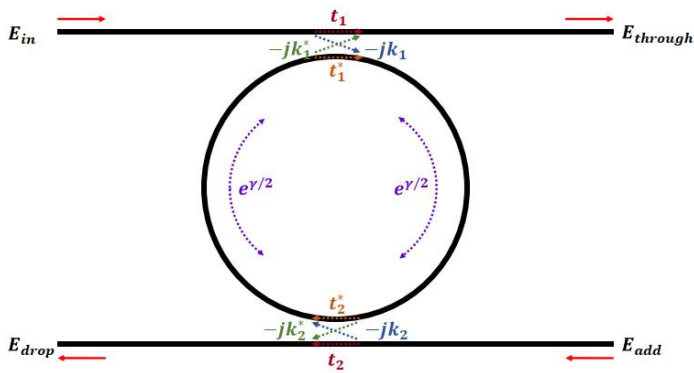
- Optical data link are vital parts of modern High Energy Physics (HEP) experiments
 - CERN experiments exploit tens of thousands of custom optical datalinks
- All these links utilize conventional discrete components
 - Directly modulated lasers and normal-incidence p-i-n photodiodes
 - Mature technologies and thoroughly studied characteristics under irradiation
- We are reaching the limits what can be done with conventional links: $\text{few} \times 10^{15} \text{ n/cm}^2$
- The placement already restricted by radiation levels during the experiment lifetime

**The final runs of High-Luminosity
LHC and future accelerators
require even higher levels of
radiation tolerance**

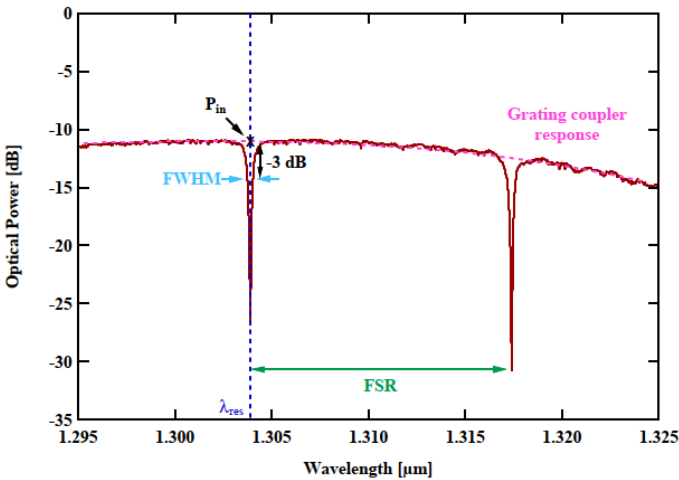




(a) All-Pass.



(b) Add-Drop.



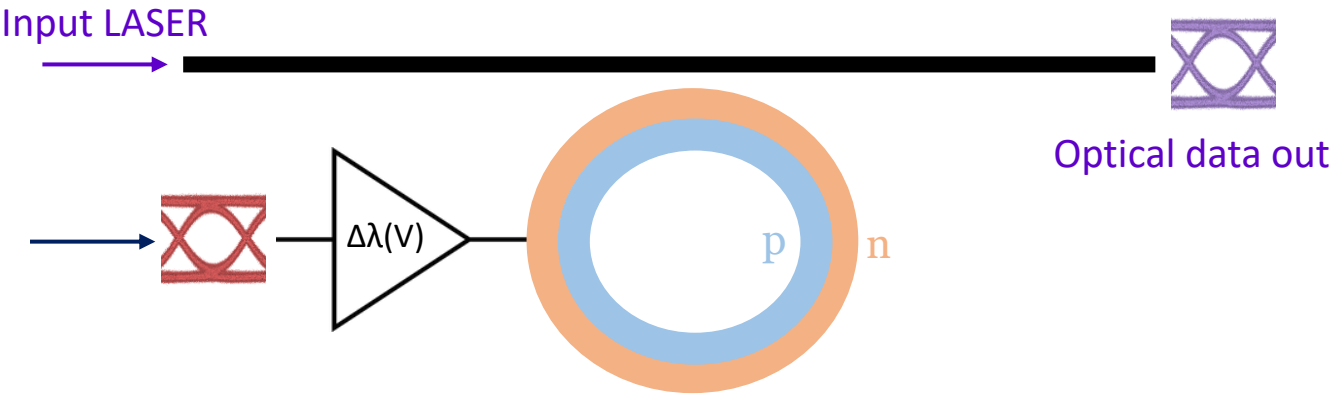
(b)

Figure 4: (a) All-pass configuration of the RM, with the coefficients of the electromagnetic fields. (b) Optical spectrum at the output, with the characteristic resonance profiles.

Figure 1.5: (a) All-pass and (b) add-drop configurations of the ring resonator, with the coefficients for the evanescent and transmitted electromagnetic fields.

$$\Delta n = \Delta n_e + \Delta n_h = - \left[8.8 \cdot 10^{-22} \Delta N_e + 8.5 \cdot 10^{-18} (\Delta N_h)^{0.8} \right],$$

$$\Delta \alpha = \Delta \alpha_e + \Delta \alpha_h = 8.5 \cdot 10^{-18} \Delta N_e + 6.0 \cdot 10^{-18} \Delta N_h,$$



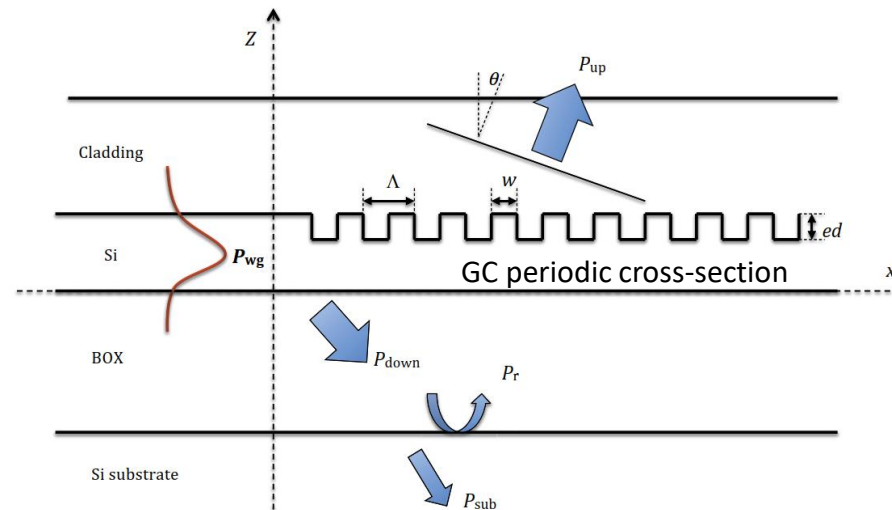
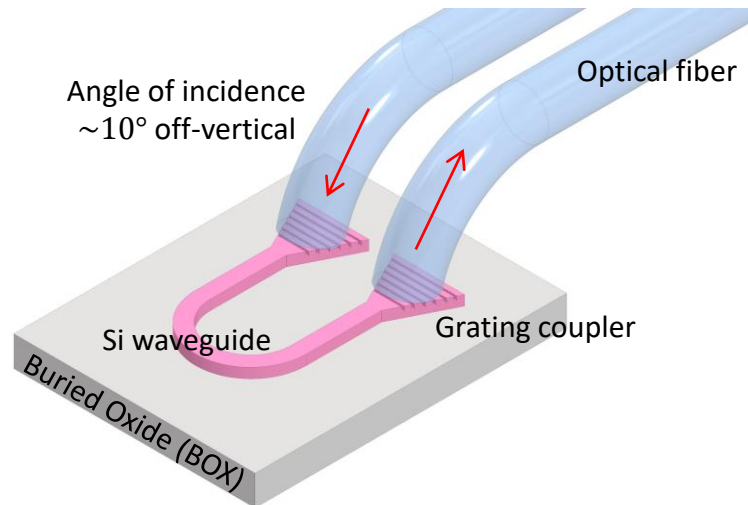
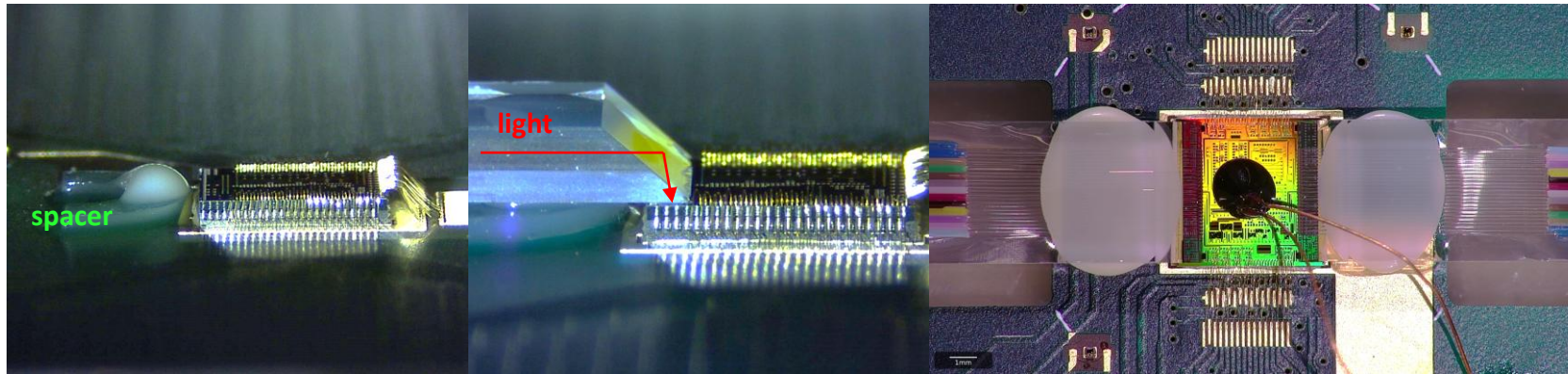
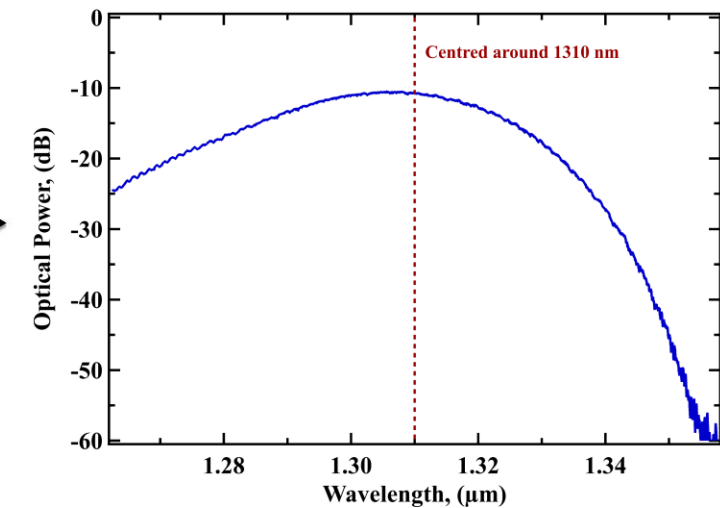
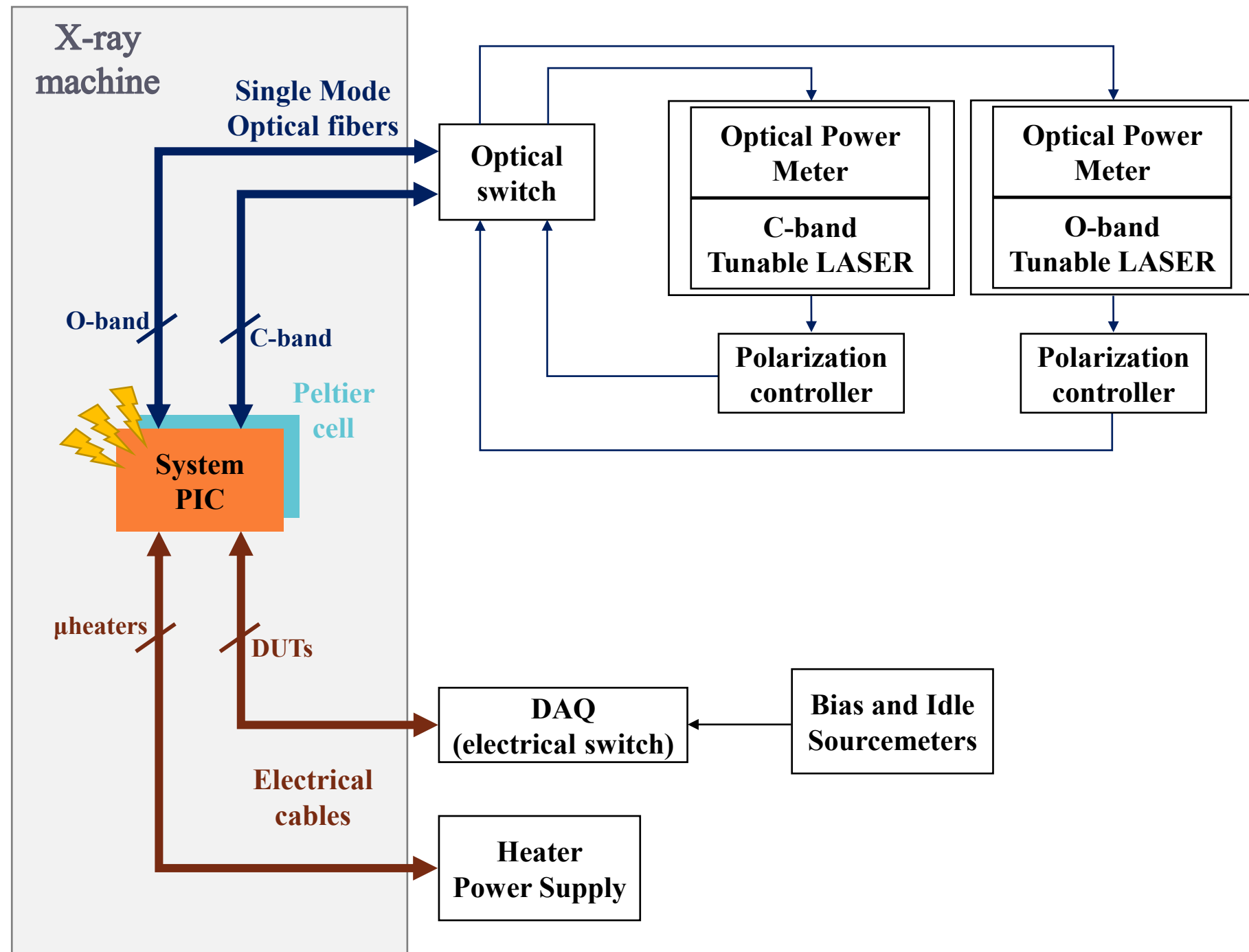


Figure 5.1 Schematic cross-section diagram of a grating coupler.

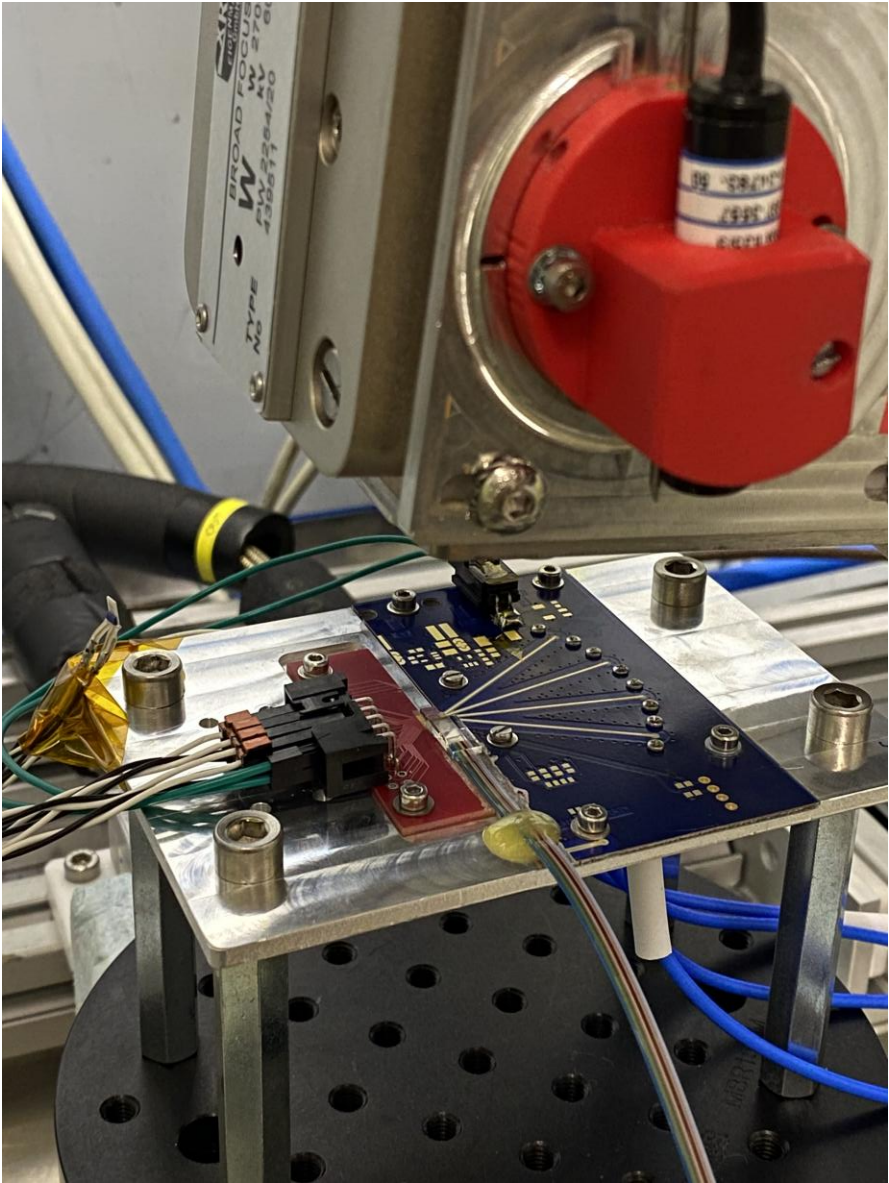
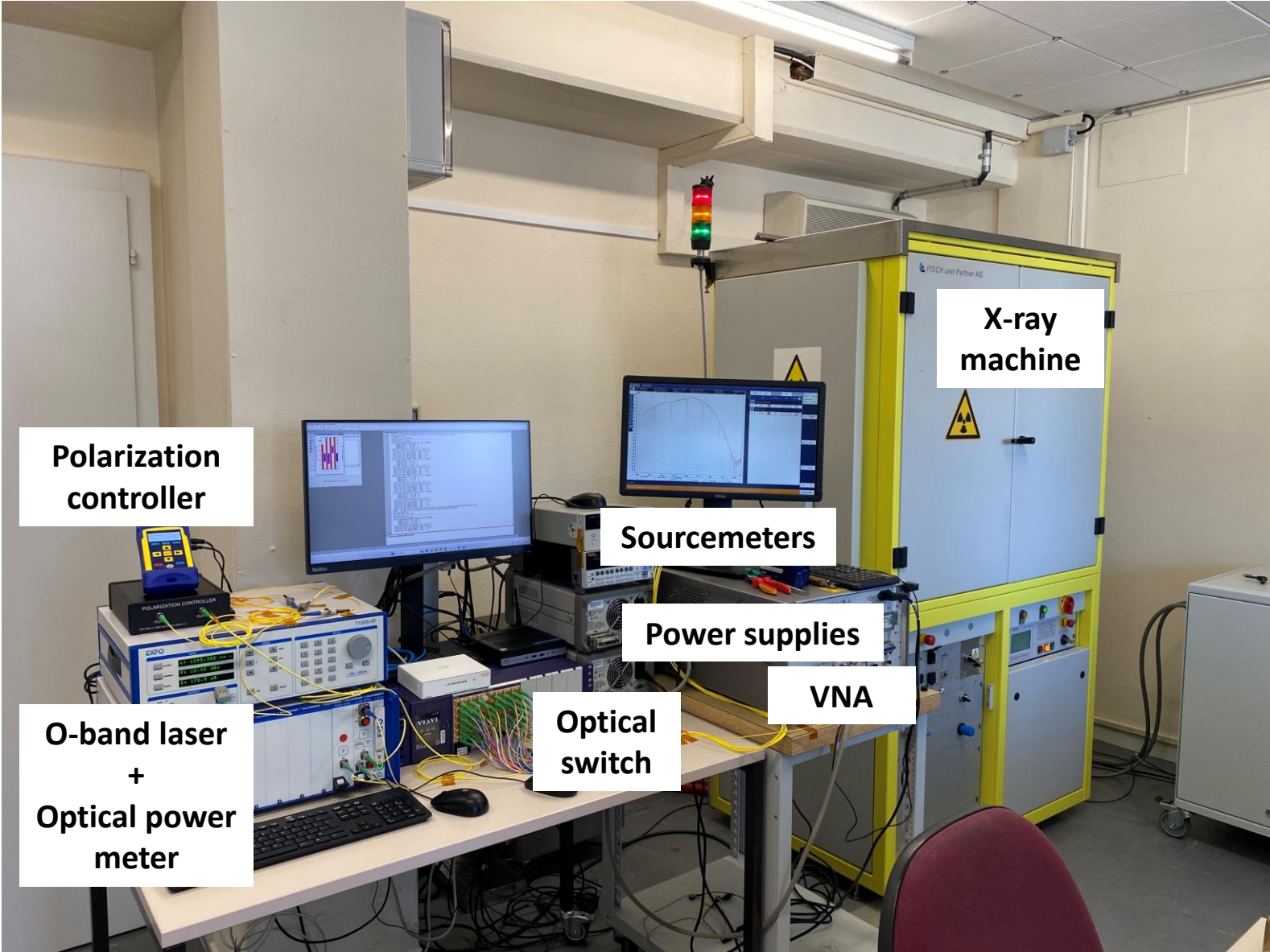
*<https://doi.org/10.1017/CBO9781316084168.006>

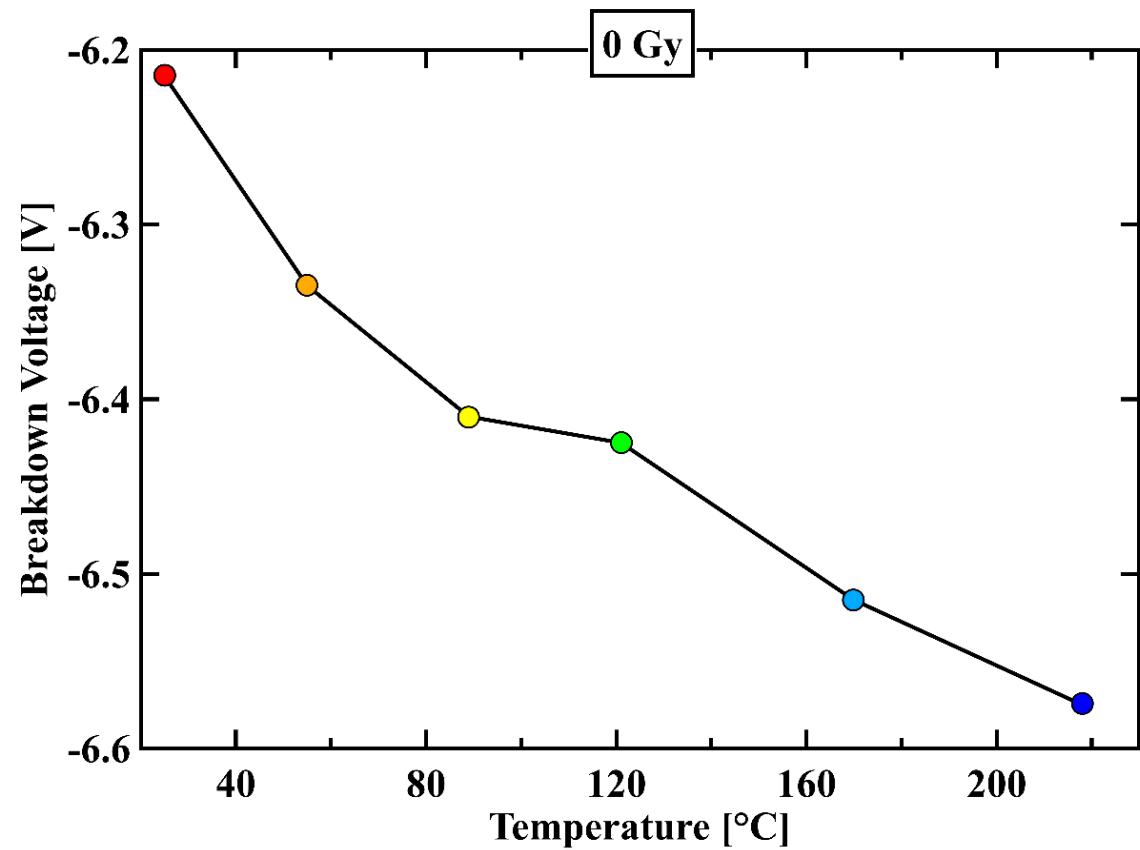
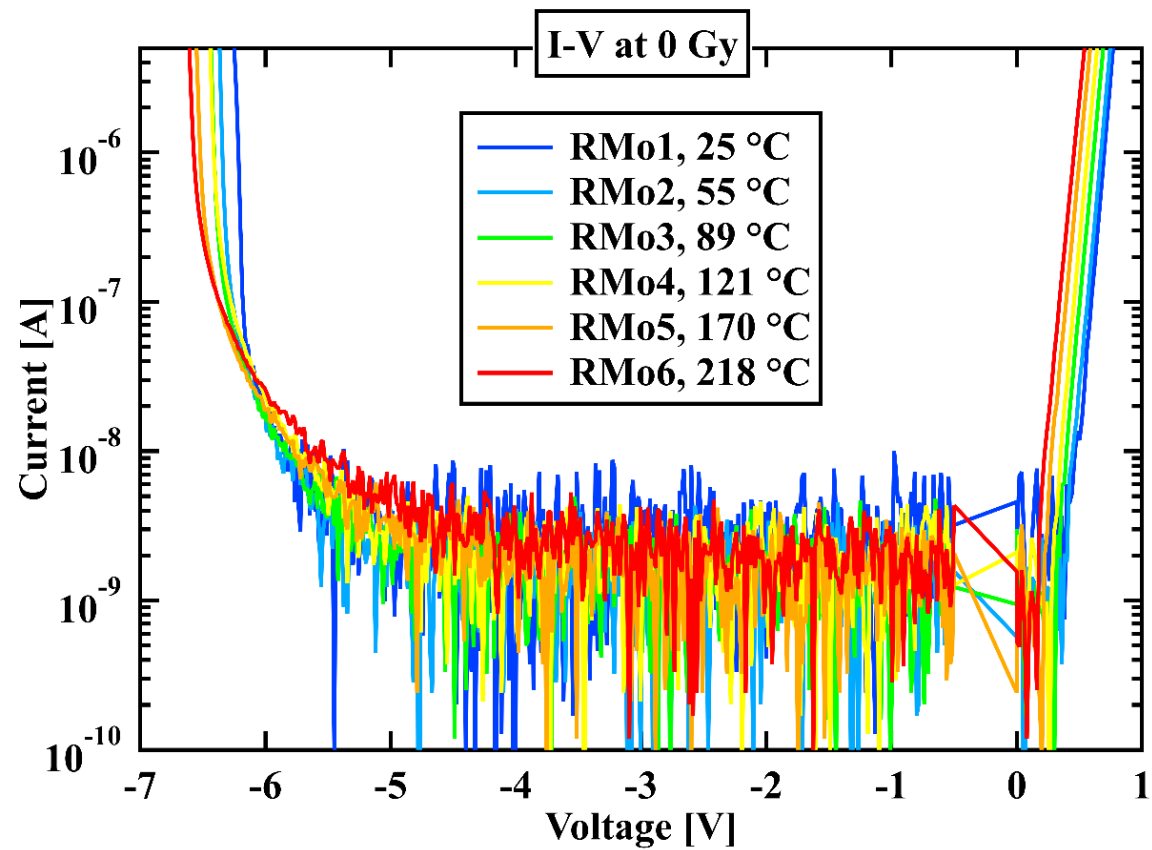


Static X-ray Test Setup

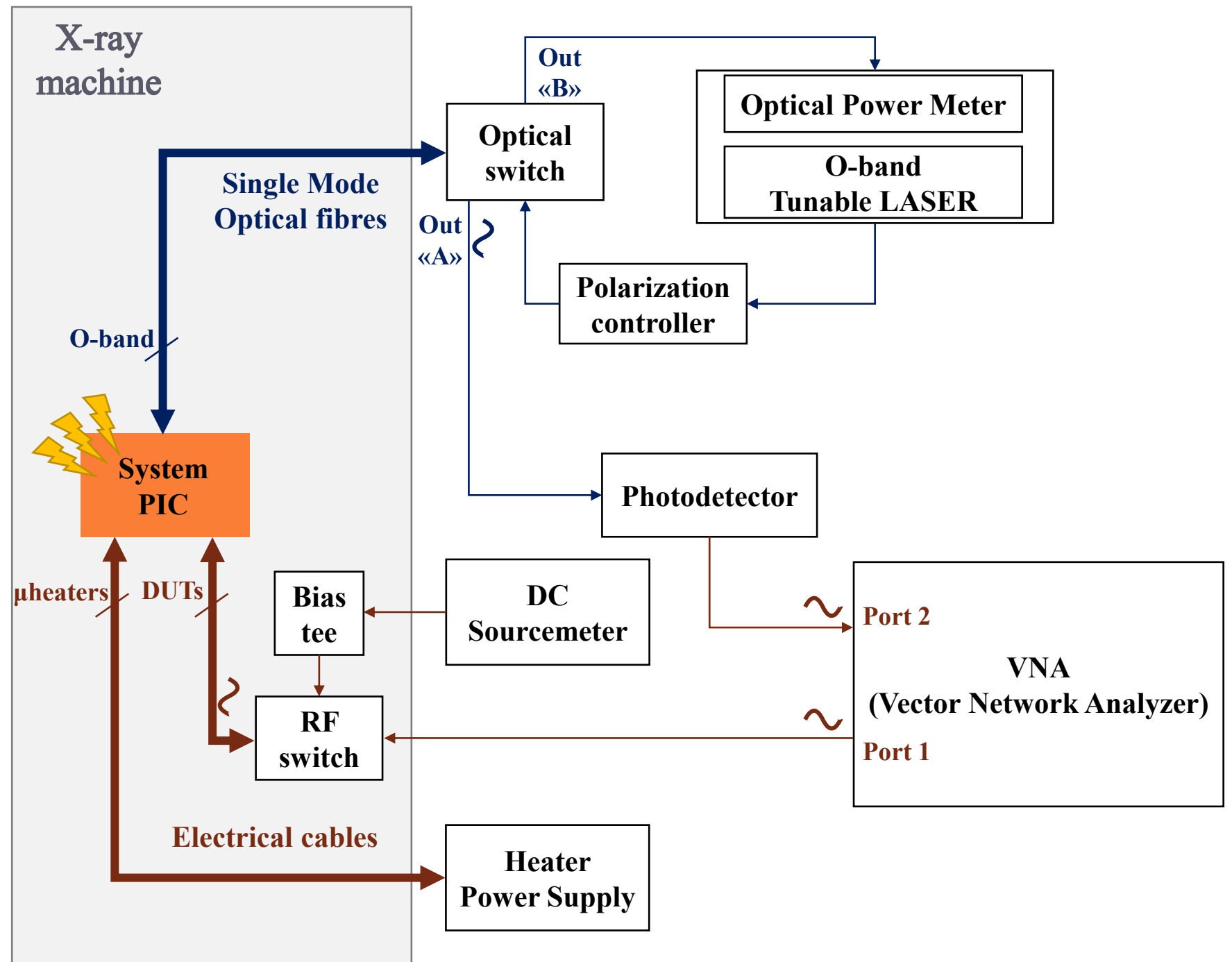


Static X-ray Test – Setup

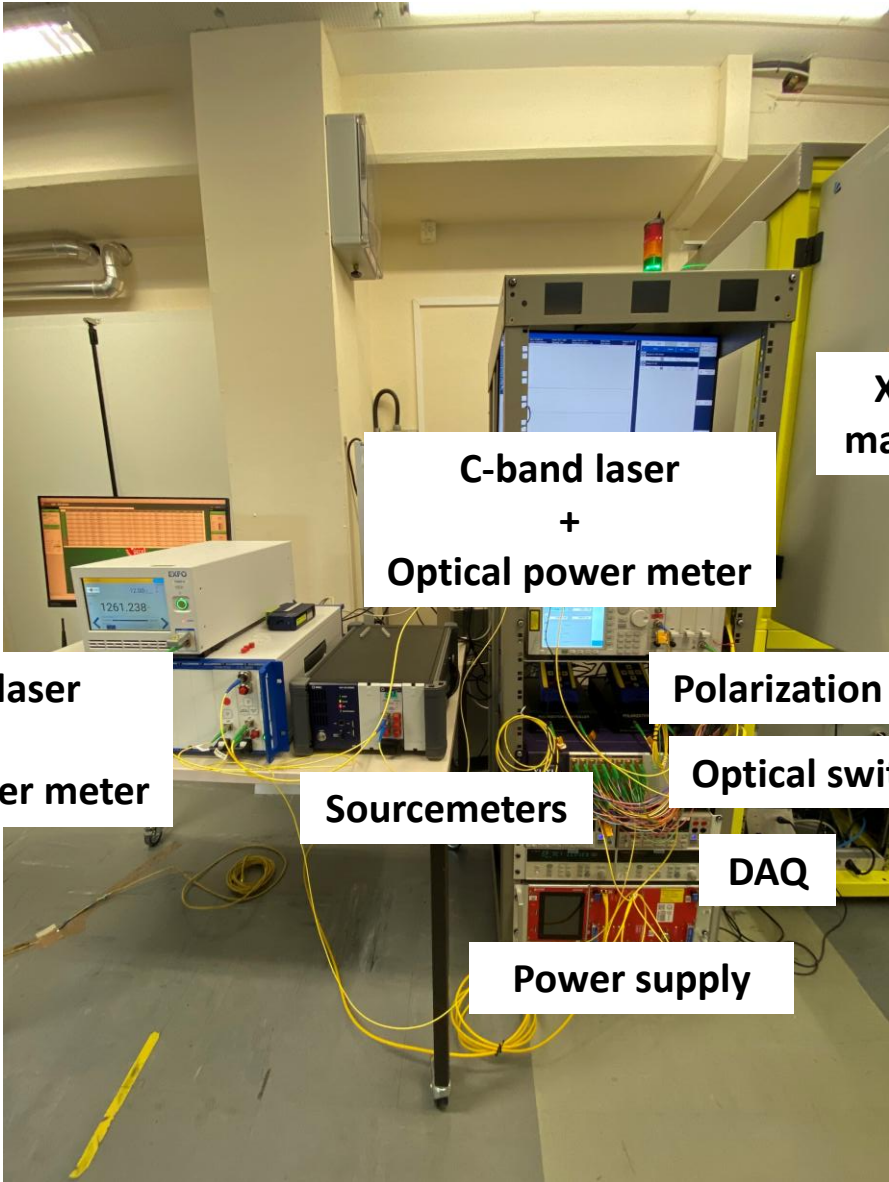




Dynamic X-ray Test Setup



Dynamic X-ray Test – Setup



X-ray
machine

C-band laser
+
Optical power meter

O-band laser
+
Optical power meter

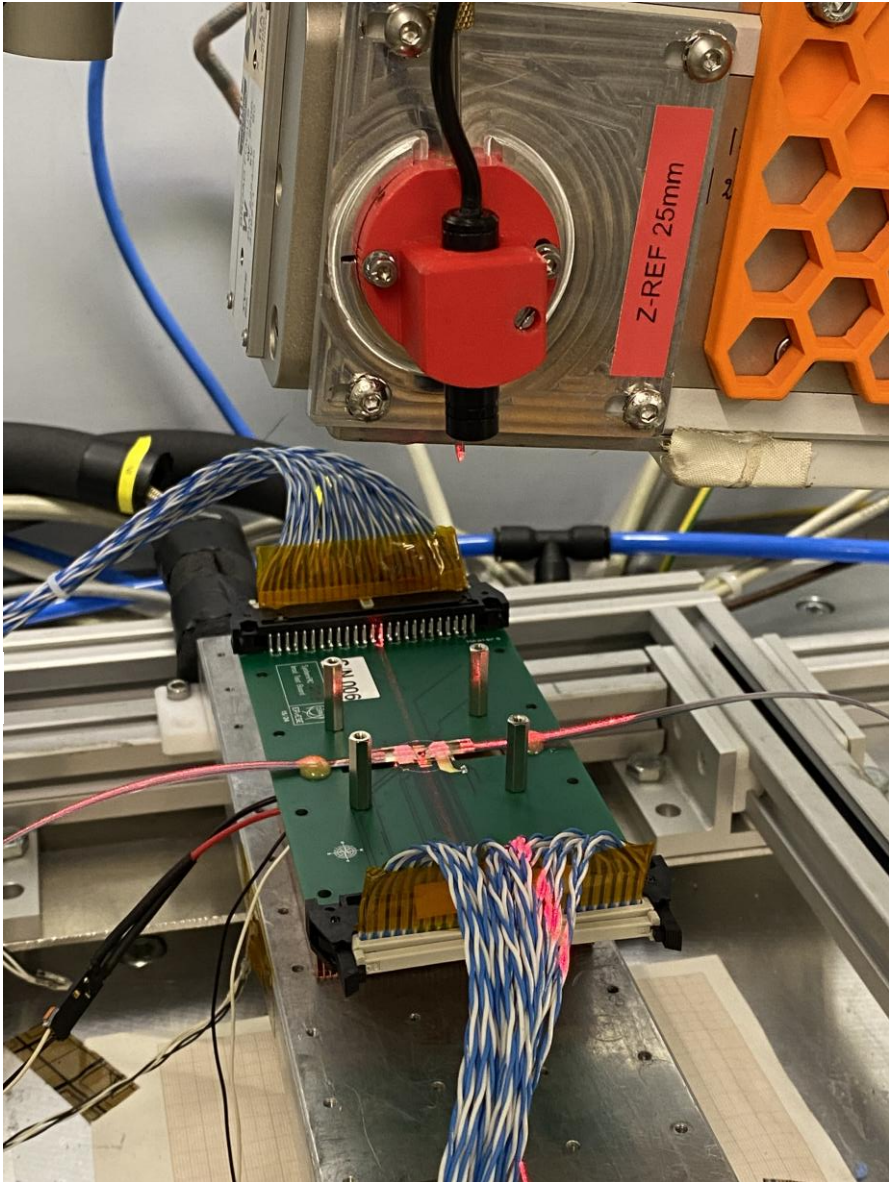
Polarization controllers

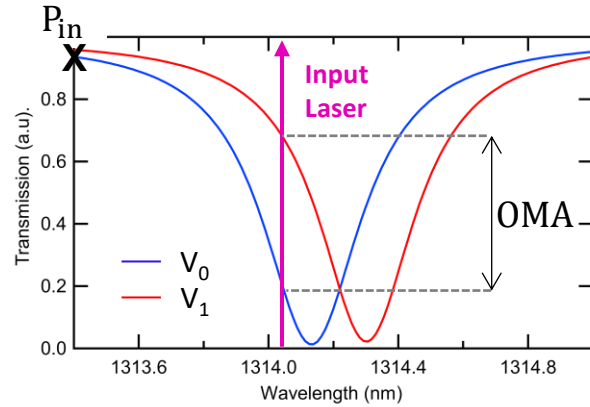
Optical switch

Sourcemeters

DAQ

Power supply

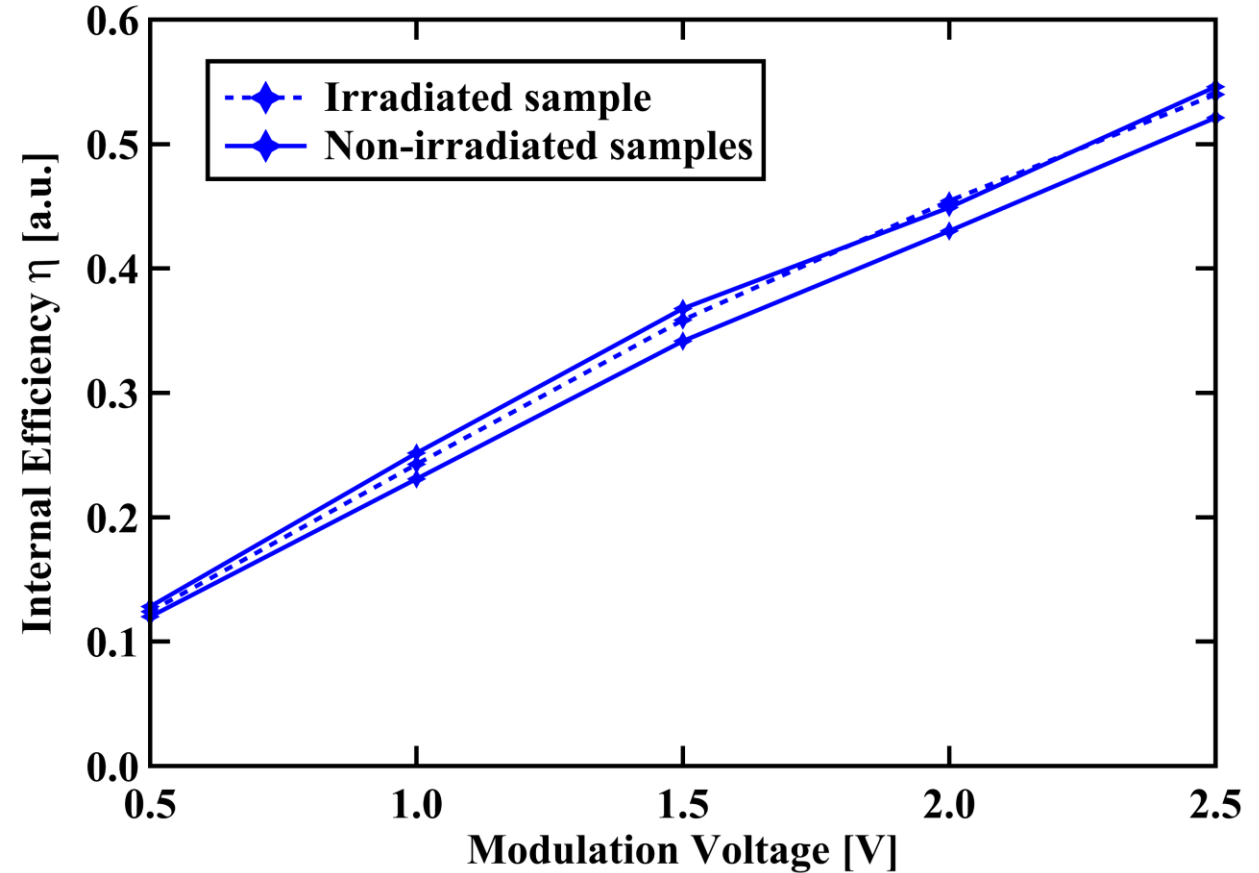


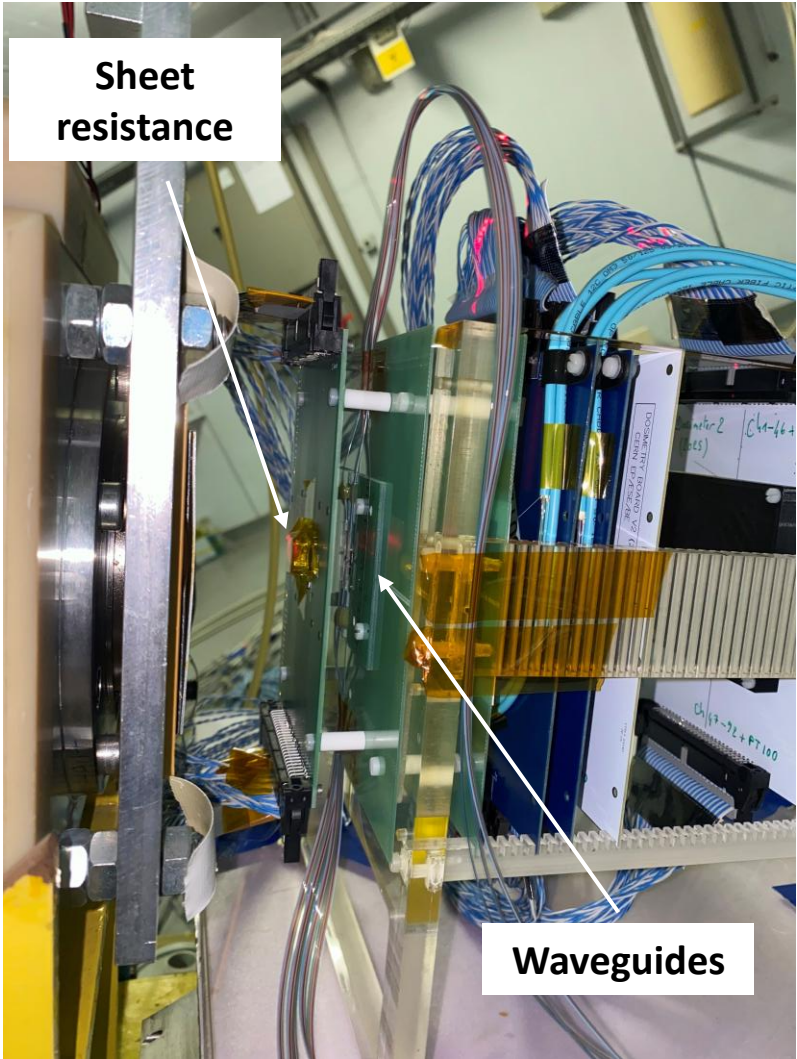
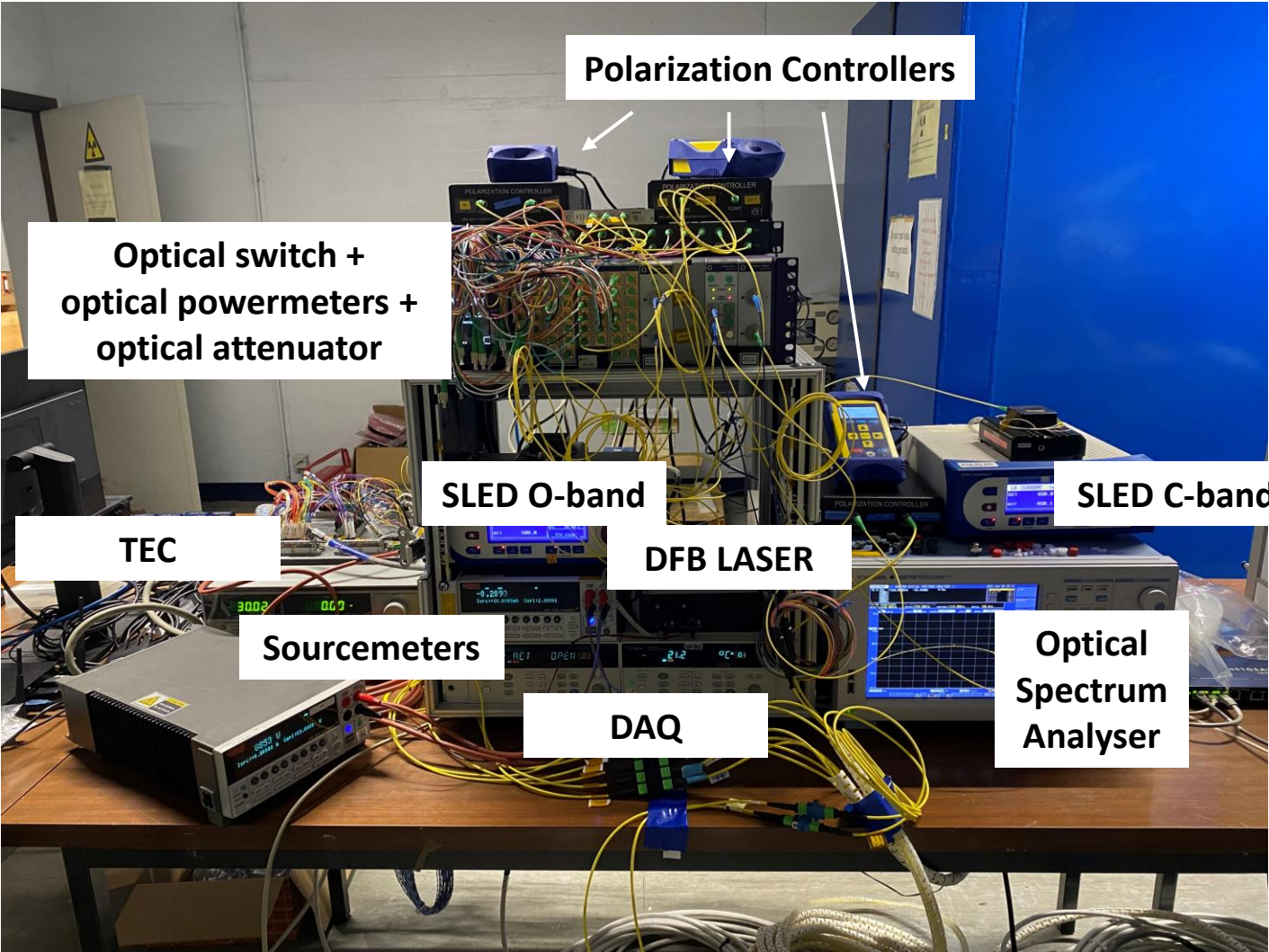


RM efficiency, defined as:

$$\eta(V_{\text{mod}}) = \frac{\text{OMA}}{P_{\text{in}}},$$

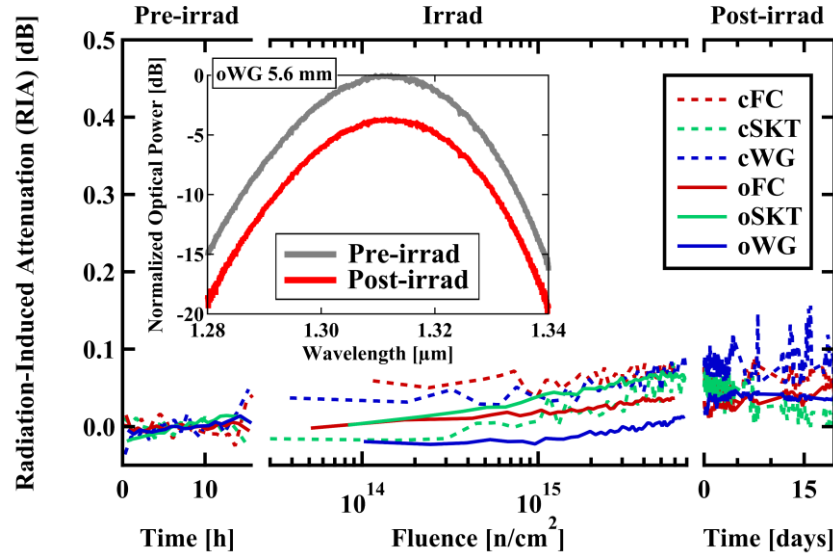
of the irradiated sample **did not change after exposure to 12.3 MGy**, following the annealing procedure



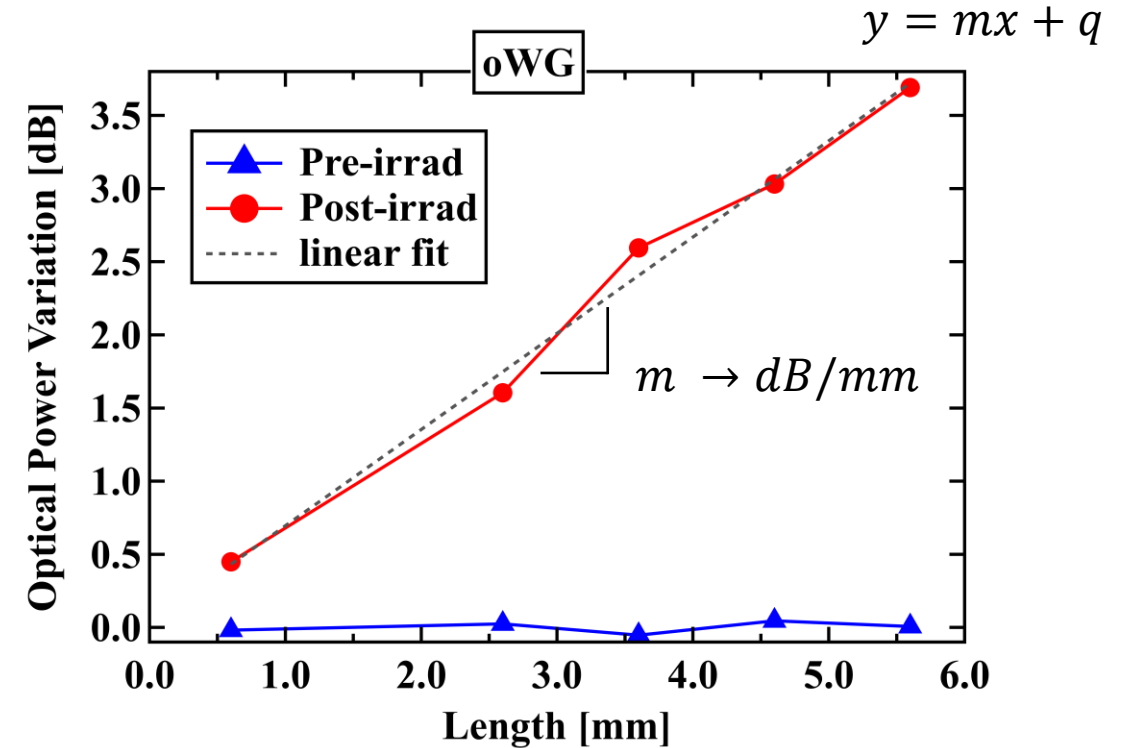


Beam distance: 4.5 cm for sheet resistance - 6.05 cm for cSKT, cWG, oSKT, oWG – 6.65 cm for cFC, oFC, Nonlinearity

$q \rightarrow y - \text{intercept} \rightarrow \text{grating coupler}$



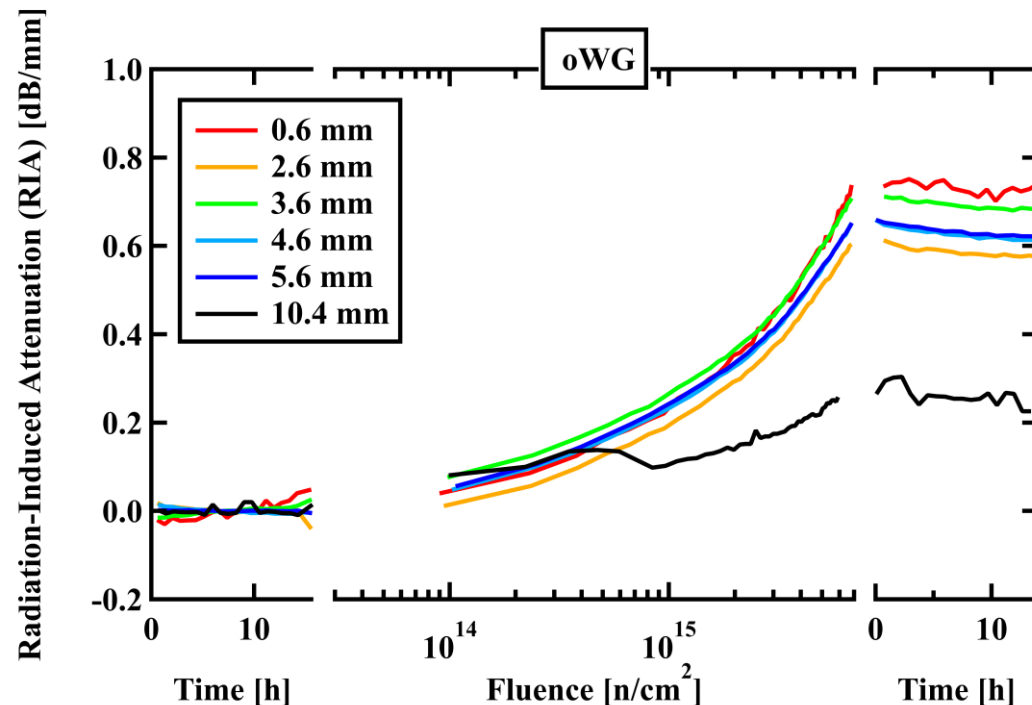
Analogous phenomena are observed in other applications, such as defect-based photon emitters for quantum computing, where several defect complexes exhibit emission in the O-band. In particular, T-, I-, and G-centers all show emission at photon energies around 0.95 eV [24]. These defects, commonly referred to as color centers, are typically generated in silicon through carefully controlled temperature and irradiation procedures, and they are used as emitters around cryogenic temperatures. While their formation in clusters due to high-energy neutron irradiation has not been directly demonstrated, it could plausibly contribute to increased absorption around 1.31 μm , especially considering the lack of silicon-based emitters in the C-band [25]. Identifying the specific mechanisms responsible for this absorption is beyond the scope of the present work, but future studies could provide further insight into the wavelength-dependent effects of neutron-induced defects in SiPh structures.



- [24] P. P. Filippatos, A. Chroneos, and C. A. Londos, "Re-examination of important defect complexes in silicon: From microelectronics to quantum computing," *Journal of Applied Physics*, vol. 137, no. 23, p. 230701, 06 2025. [Online]. Available: <https://doi.org/10.1063/5.0276550>
- [25] G. Andriani, F. Amanti, F. Armani, V. Bellani, V. Bonaiuto, S. Cammarata *et al.*, "Solid-state color centers for single-photon generation," *Photonics*, vol. 11, no. 2, 2024. [Online]. Available: <https://www.mdpi.com/2304-6732/11/2/188>

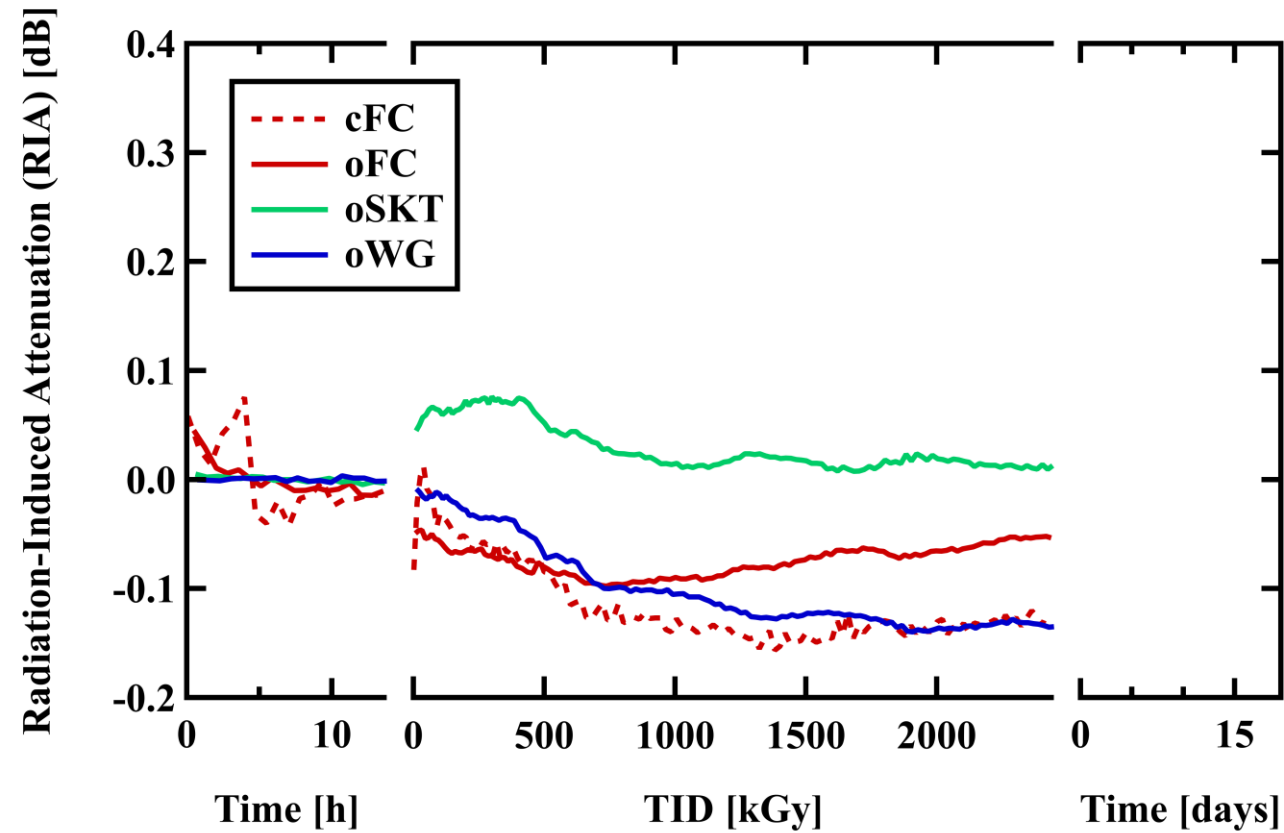


If we plot the increase in linear loss together with the RIA coefficient for the oWG waveguides, the discrepancy between the two measurements becomes evident.



The RIA coefficient, calculated from the increase in linear loss for the 10.4 mm sample, shows a much smaller increase with neutron fluence compared to the other waveguides. This is likely due to a photobleaching effect that induces partial annealing in the waveguide when high optical power is injected. This observation should be emphasized in a potential publication, as it is both important for understanding the behaviour of the device. However, at the same time, this is promising for our application, since it indicates that the calculated RIA coefficient is likely an overestimation.

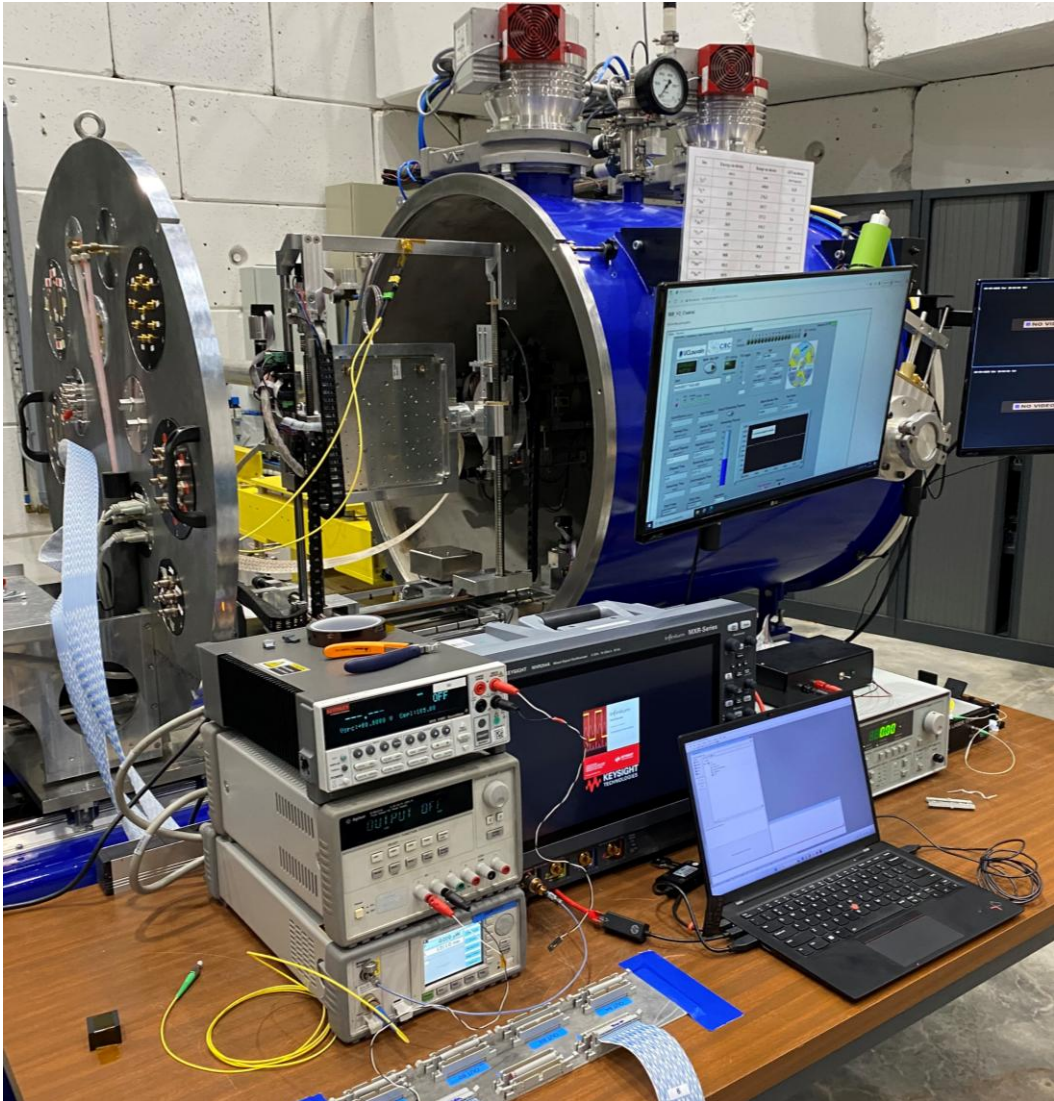
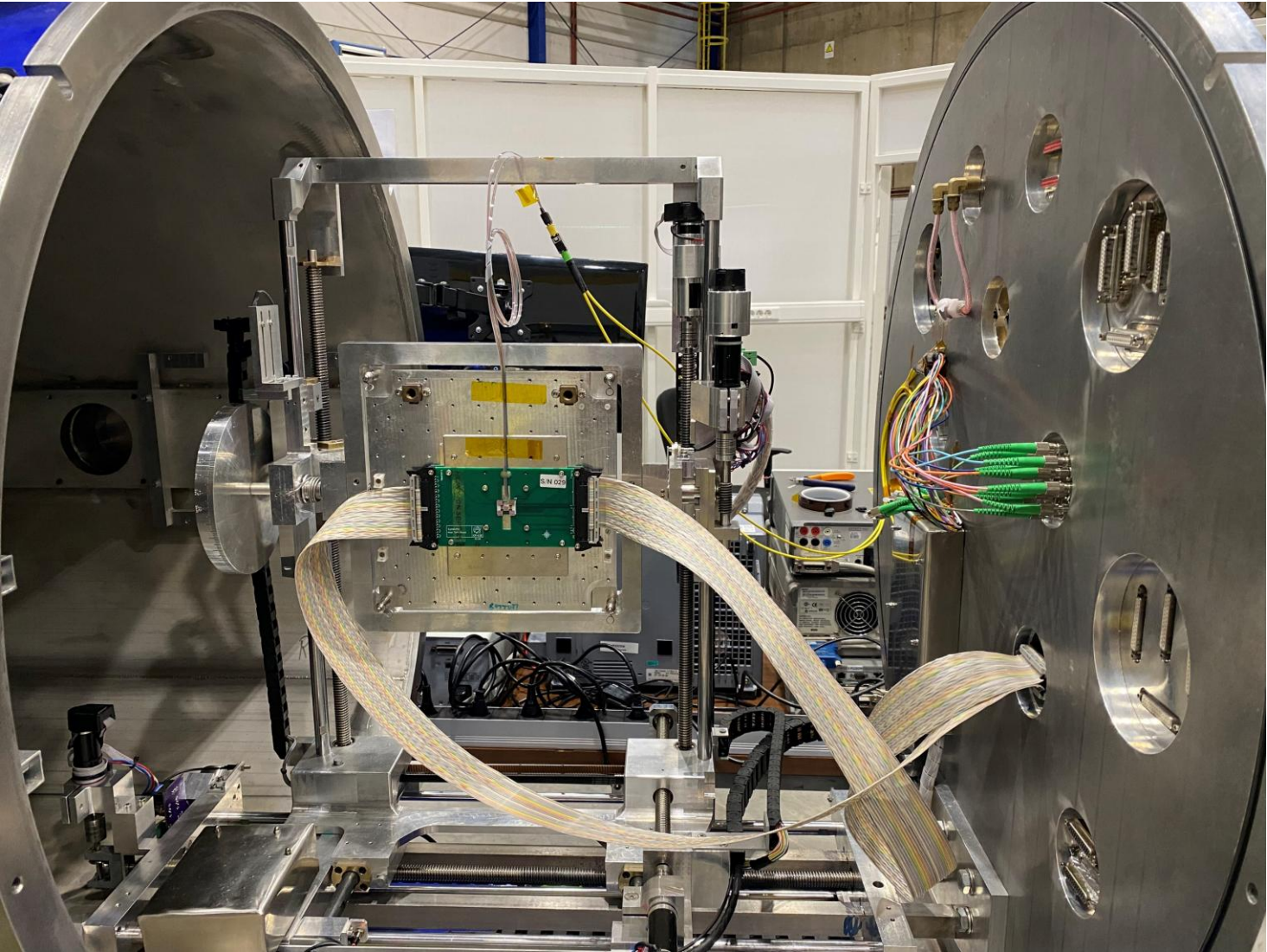
N.B. For a mistake in the acquisition loop, I forgot to set the attenuation to 25dB in the idle time, that's why we have this annealing effect. The power into the waveguide during the test was ~ 14.9 mW (calculated from P_o). Even if this was a mistake, it actually gives us an extra data point which is really useful.



Heavy ion test – Setup

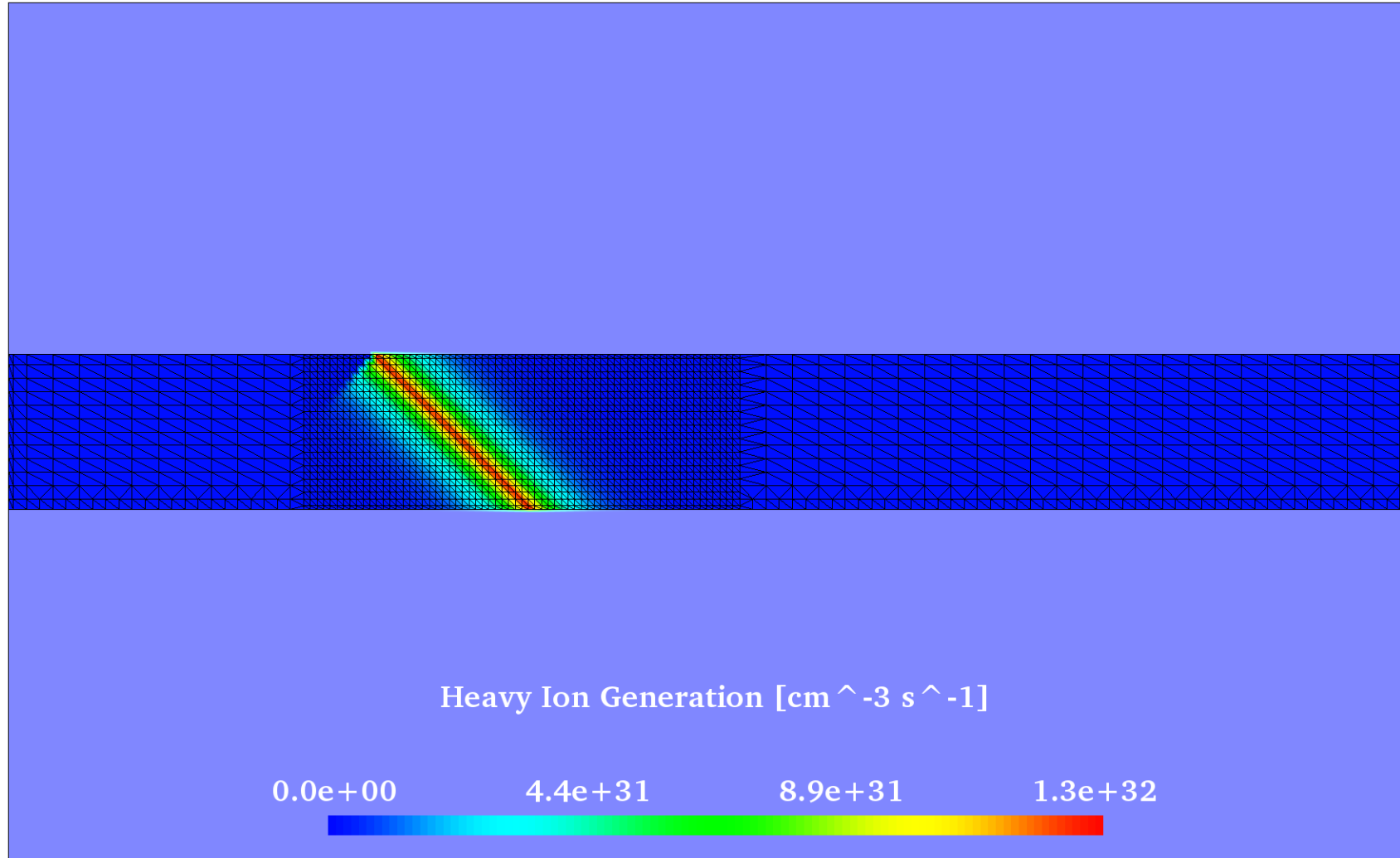


UNIVERSITY OF
BIRMINGHAM



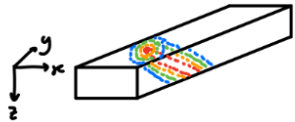


TCAD mesh





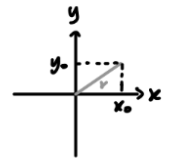
We have to imagine that $N(r)$ is a 2D exponential function which describes the carrier generation along the ion propagation. The carrier generated are considered uniform along the penetration direction:



We can consider one plane along z . The carrier generated are:

$$N(r) = N_0 \cdot e^{-r/\sigma_{ion}} \quad \text{where } N_0 = N(x=0, y=0)$$

Therefore, for each coordinate point the radius can be described as:



$$r = \sqrt{x_0^2 + y_0^2}$$

By building a mesh grid on MATLAB, the 2D carrier density is given by:

$$N(x, y) = N_0 \cdot e^{-\sqrt{x_0^2 + y_0^2}/\sigma_{ion}}$$

To get (8), I need to take the radial section using cylindrical coordinates:

$$\iint N(x, y) dx dy \quad ; \quad r = \sqrt{x^2 + y^2} \quad ; \quad x = r \cos \theta \quad ; \quad y = r \sin \theta$$

we need to change the coordinates by calculating the Jacobian:

$$dx dy = |J| dr d\theta$$

$$J = \begin{vmatrix} \partial x / \partial r & \partial x / \partial \theta \\ \partial y / \partial r & \partial y / \partial \theta \end{vmatrix} = \begin{vmatrix} \cos \theta & -r \sin \theta \\ \sin \theta & r \cos \theta \end{vmatrix} = (\cos \theta \cdot r \cos \theta) - (-r \sin \theta \cdot \sin \theta) = r \cos^2 \theta + r \sin^2 \theta = r$$

$$\Rightarrow dx dy = r dr d\theta = dA$$

The integral becomes:

$$\iint N(x, y) dx dy = \int_S N(r) dA = \int_0^{2\pi} \int_0^{+\infty} N(r) \cdot r dr d\theta,$$

since $N(r)$ does not depend on $\theta \Rightarrow \int_0^{2\pi} d\theta = 2\pi$

$$\Rightarrow 2\pi \int_0^{+\infty} r \cdot N(r) dr = 2\pi N_0 \int_0^{+\infty} r \cdot e^{-r/\sigma_{ion}} dr$$

$$* \quad t = \frac{r}{\sigma_{ion}} \Rightarrow r = t \cdot \sigma_{ion} \Rightarrow dr = \sigma_{ion} dt, \text{ for } r \rightarrow +\infty \text{ also } t \rightarrow +\infty$$

$$\Rightarrow 2\pi N_0 \int_0^{+\infty} t \cdot \sigma_{ion} e^{-t} \cdot \sigma_{ion} dt = 2\pi N_0 \sigma_{ion}^2 \int_0^{+\infty} t \cdot e^{-t} dt$$

$$* \quad \int f \cdot g' = f \cdot g - \int f' \cdot g \Rightarrow f = t \text{ and } g' = e^{-t}$$

$$\Rightarrow \int t \cdot e^{-t} dt = t \cdot (-e^{-t}) - \int (-e^{-t}) dt = -t \cdot e^{-t} + \int e^{-t} dt$$

$$\Rightarrow 2\pi N_0 \sigma_{ion}^2 \int_0^{+\infty} t \cdot e^{-t} dt = 2\pi N_0 \sigma_{ion}^2 \left[-t \cdot e^{-t} - e^{-t} \right]_0^{+\infty} = 2\pi N_0 \sigma_{ion}^2 \left[-(t+1)e^{-t} \right]_0^{+\infty}$$

$$* \quad \lim_{t \rightarrow +\infty} -(t+1) \cdot e^{-t} \rightarrow 0 \quad \text{exponential has higher order of infinity than polynomial}$$

$$\lim_{t \rightarrow 0} -(t+1) e^{-t} \rightarrow -1$$

$$\Rightarrow 2\pi N_0 \sigma_{ion}^2 \left[0 - (-1) \right] = 2\pi N_0 \sigma_{ion}^2 \Rightarrow \iint N(x, y) dx dy = 2\pi N_0 \sigma_{ion}^2$$



$$\frac{LET \cdot \rho_{Si}}{\epsilon_{ehp}} = \frac{eV \cdot cm^2}{g} \cdot \frac{g}{m^3} \cdot \frac{pair}{eV} = \left[\frac{pair}{m} \right] \text{ i.e. the pairs generated per unit of length}$$

This number can be converted in charge linear density:

$$\frac{LET \cdot \rho_{Si}}{\epsilon_{ehp}} = 2\pi N_0 \sigma_{ion}^2 = \frac{Q_0}{h}, \text{ where } Q_0 \text{ is the total number of ehp generated}$$

You can see it starting from the result of the integral:

$$\int_0^{+\infty} N(r) dr = 2\pi N_0 \sigma_{ion}^2 \text{ [ehp/m]} \Rightarrow \text{we calculated the \# of ehp created radially, per unit of surface, along the ion track}$$

Therefore, if we multiply our result for the height of the waferguide (in case of vertical incidence), we get the volumetric number of ehp generated (if the radial density is considered constant):

$$Q_0 = h \cdot (2\pi N_0 \sigma_{ion}^2) \Rightarrow 2\pi N_0 \sigma_{ion}^2 = \frac{Q_0}{h}$$

$$N(r) = N_0 e^{-r/\sigma_{ion}}$$

$$\frac{LET \cdot \rho_{Si}}{\epsilon_{ehp}} = 2\pi N_0 \sigma_{ion}^2 = \frac{Q_0}{h}$$

$$\frac{LET \cdot \rho_{Si}}{\epsilon_{ehp}} = 3.9455 \times 10^{10} \text{ ehp/cm}$$

$$h = 220 \text{ nm} \rightarrow Q_0 \approx 868021 \text{ ehp}$$

$$\rightarrow N_0 = \frac{Q_0}{2\pi h \sigma_{ion}^2}$$

For a defined value of σ_{ion}^2 we can find the corresponding N_0 :

$$\sigma_{ion} = 10 \text{ nm} \rightarrow N_0 \approx 6.28 \times 10^{21} \text{ ehp/cm}^3$$

$$\sigma_{ion} = 20 \text{ nm} \rightarrow N_0 \approx 1.57 \times 10^{21} \text{ ehp/cm}^3$$

$$\sigma_{ion} = 30 \text{ nm} \rightarrow N_0 \approx 6.98 \times 10^{20} \text{ ehp/cm}^3$$

—————→ Selected $\sigma_{ion} = 30 \text{ nm}$ for all simulations

